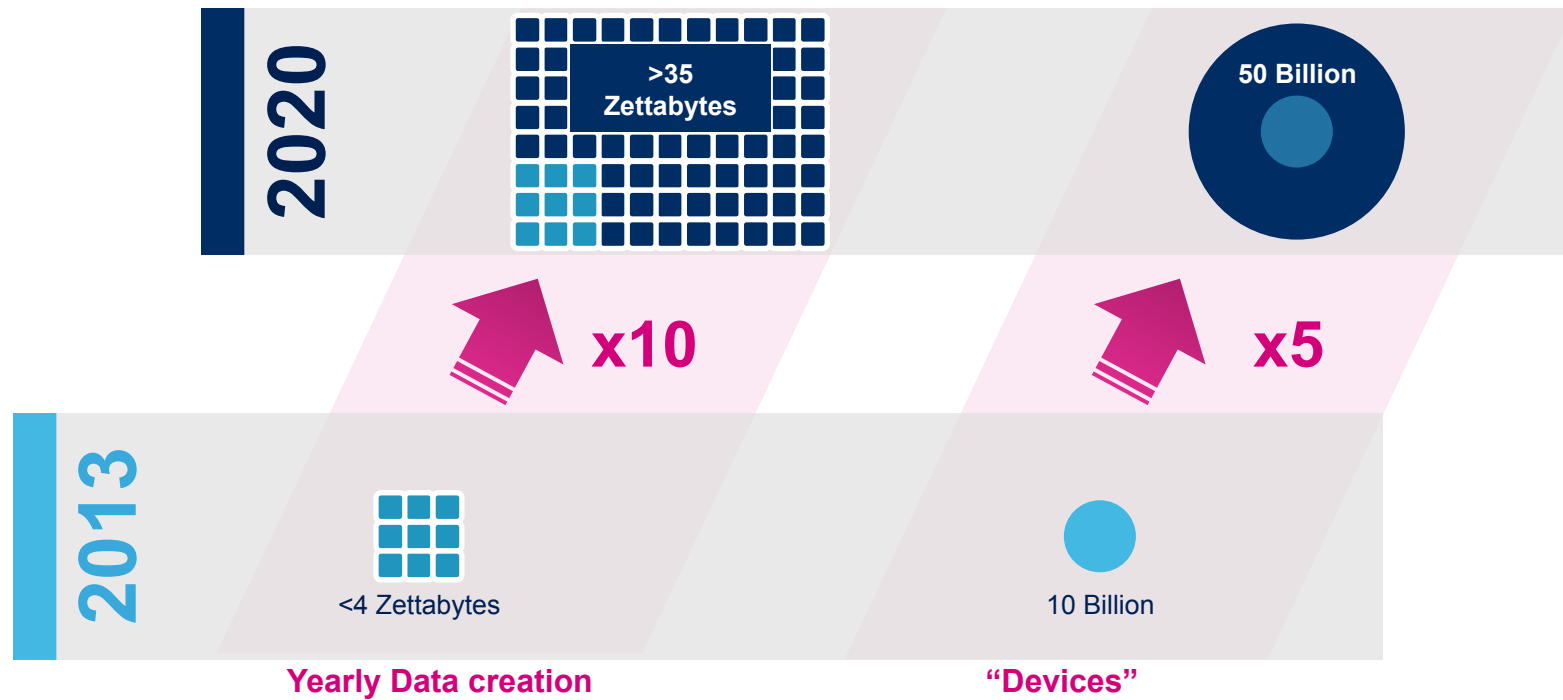




# A brief history of FD-SOI: a faster, cooler, simpler alternative technology for IoT, mobile and servers

Giorgio Cesana  
*FE Manufacturing & Technology R&D*  
*Embedded Processing Solutions*  
*STMicroelectronics*

# The Digital Explosion



A Zettabyte =  $10^{12}$  Gigabytes

# Digital Market Dynamics

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## Cloud & Network infrastructure

### Traffic & storage explosion driving

- Cloud storage & server
- Core network
- Radio access network



### Technology impact

- Network architecture
- Higher integration & performance
- Power efficiency
- Reliability

## Hubs, Gateways, Application Processors Connected devices & things

### Explosion of connected devices

- Mobility / Smartphones
- Internet of things
- Autonomous devices

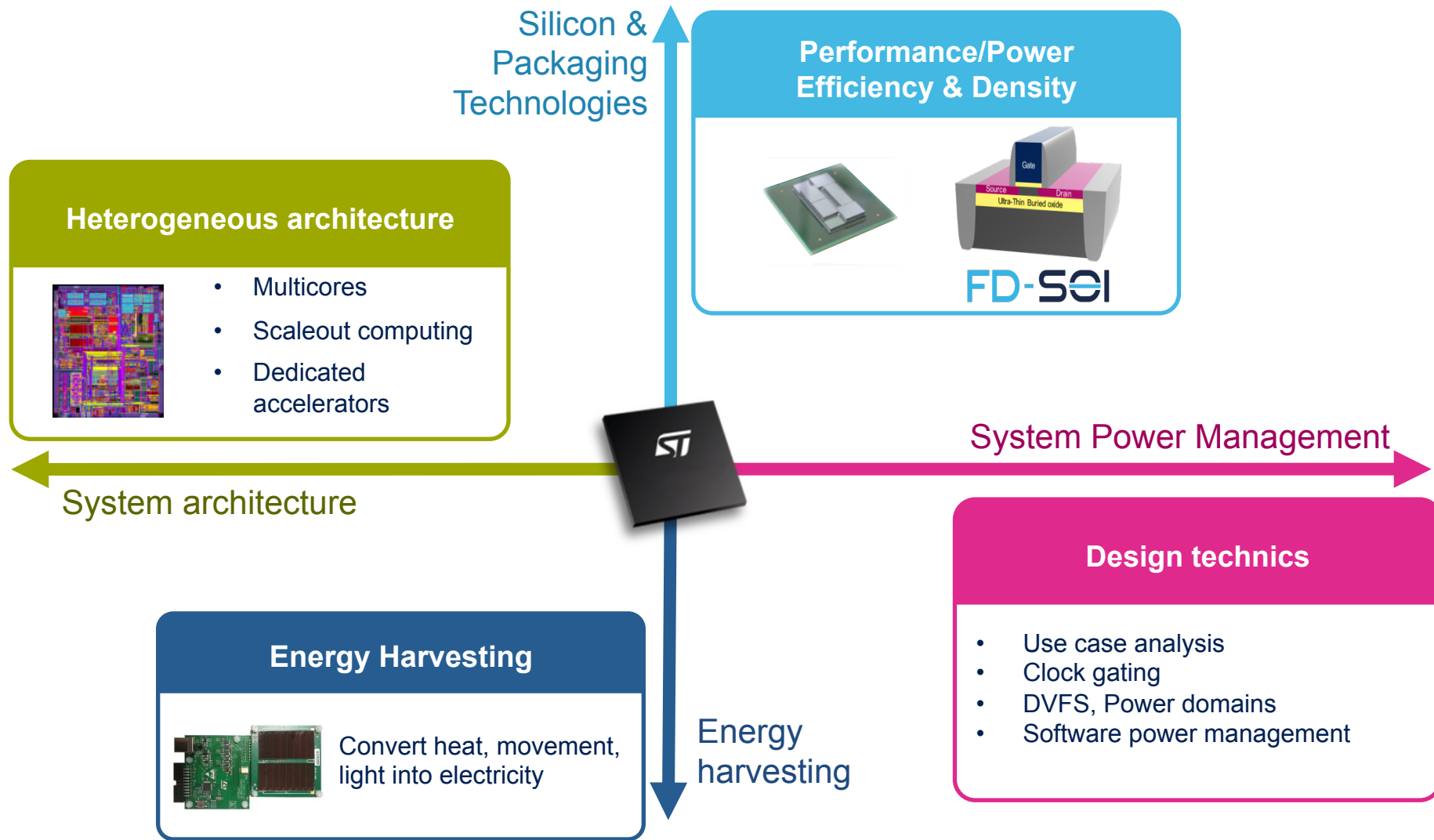


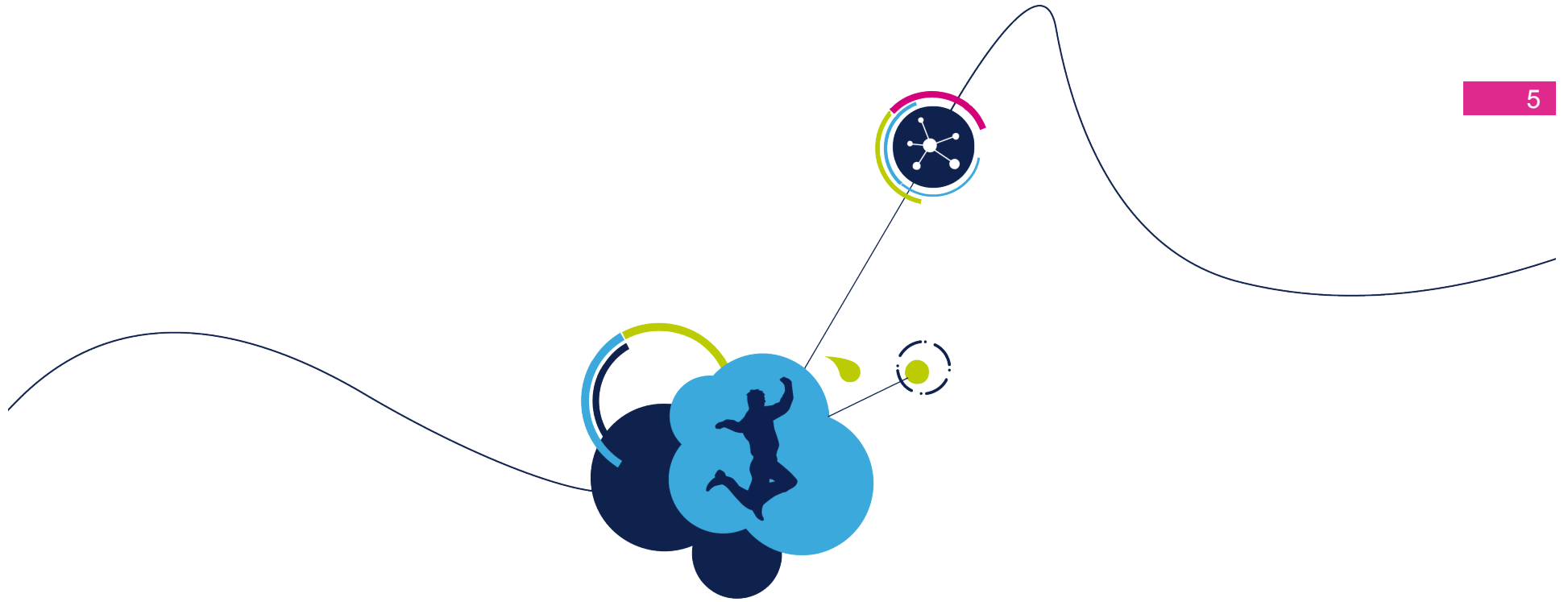
### Technology impact

- Power Autonomy
- Ultra low power sensors
- Integration Digital, RF, Power Management
- Higher performance at lower power

Explosion in connected “devices” & associated digital content  
creates a global power challenge

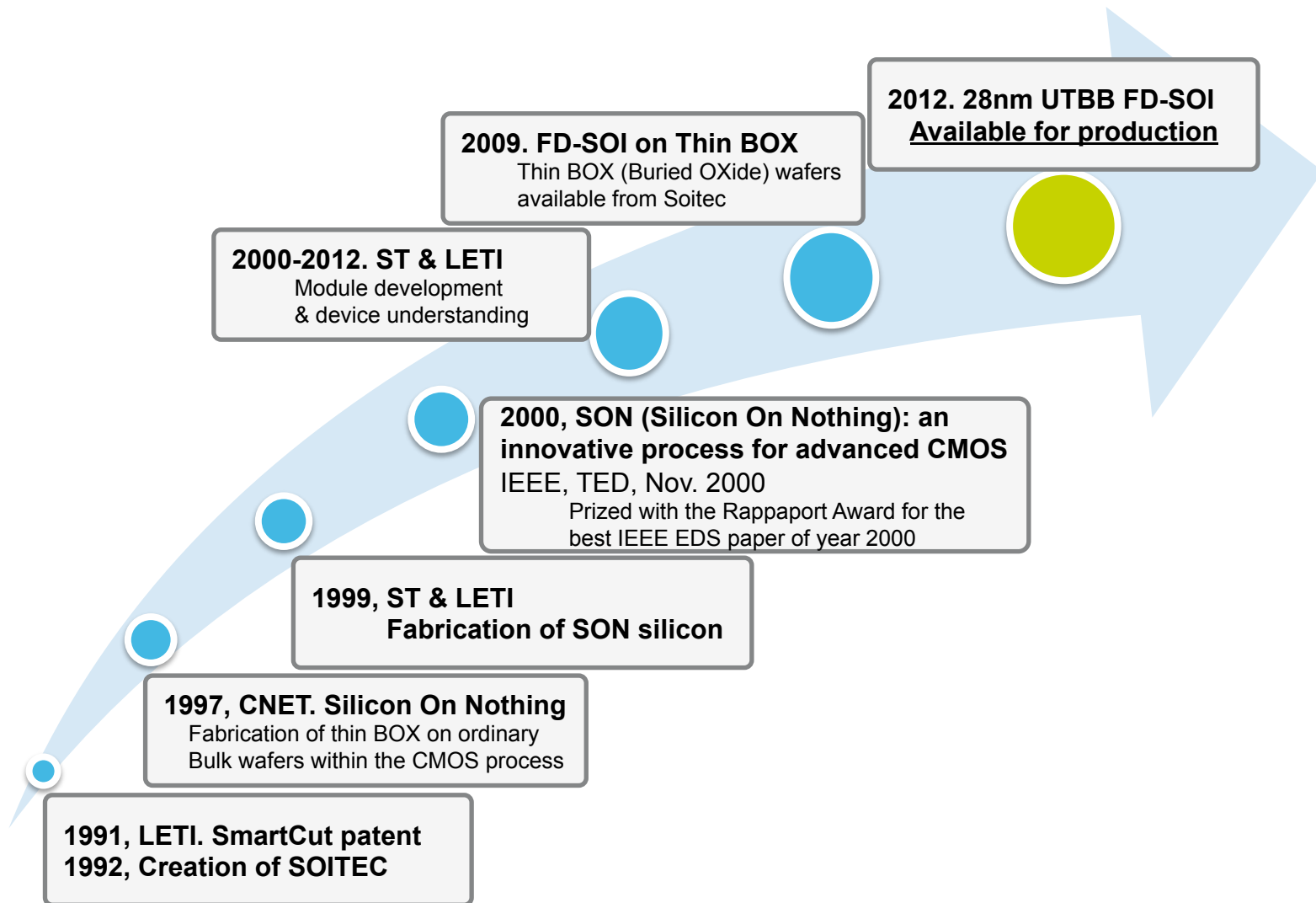
# The various aspects of power efficiency





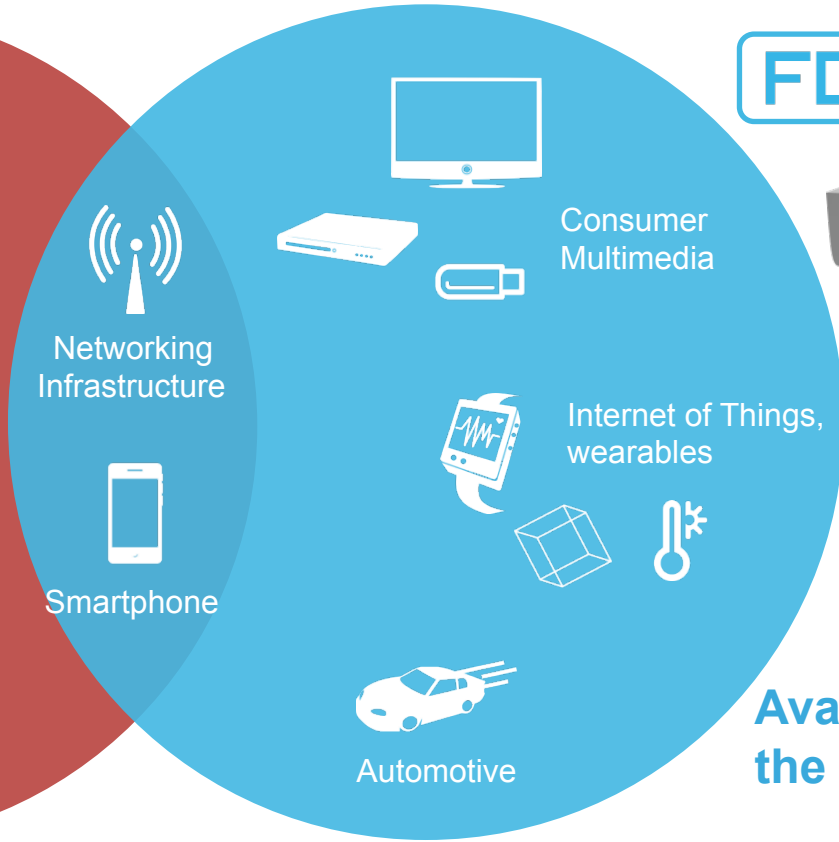
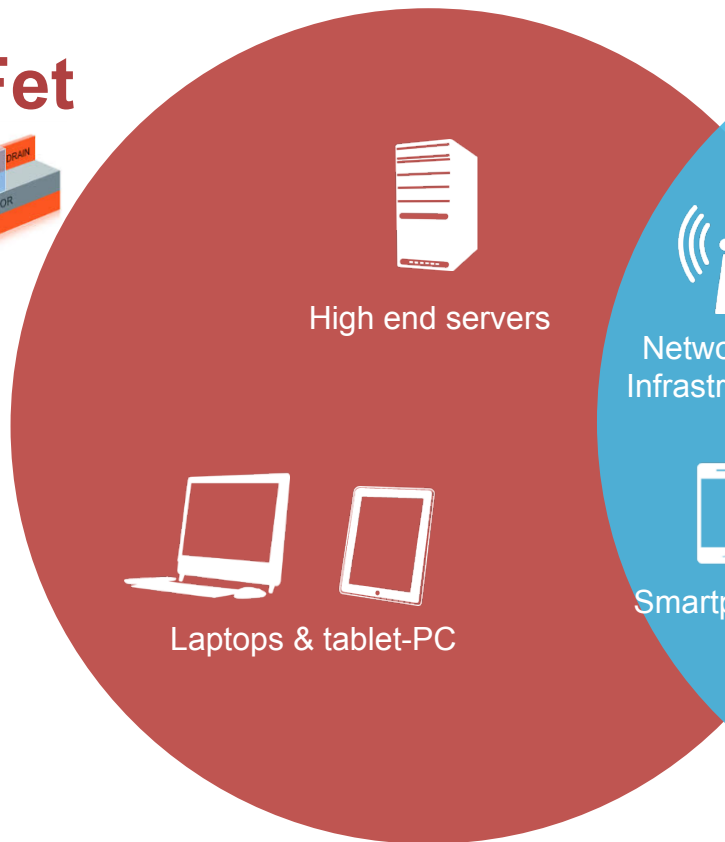
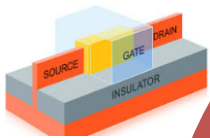
# FD-SOI Technology

# UTBB FD-SOI, A Long R&D Success Story

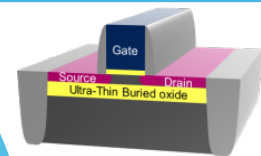


# FD-SOI addressing Power sensitive Markets

## FinFet

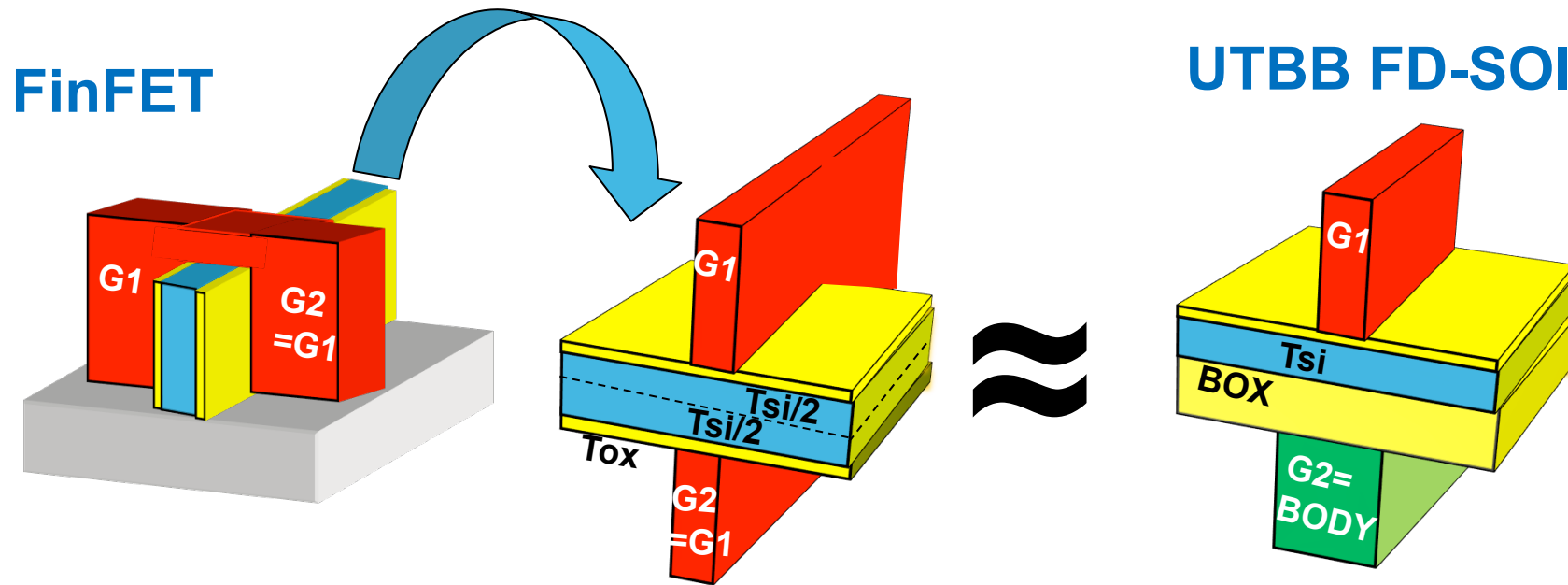


## FD-SOI



Available from the 28nm node

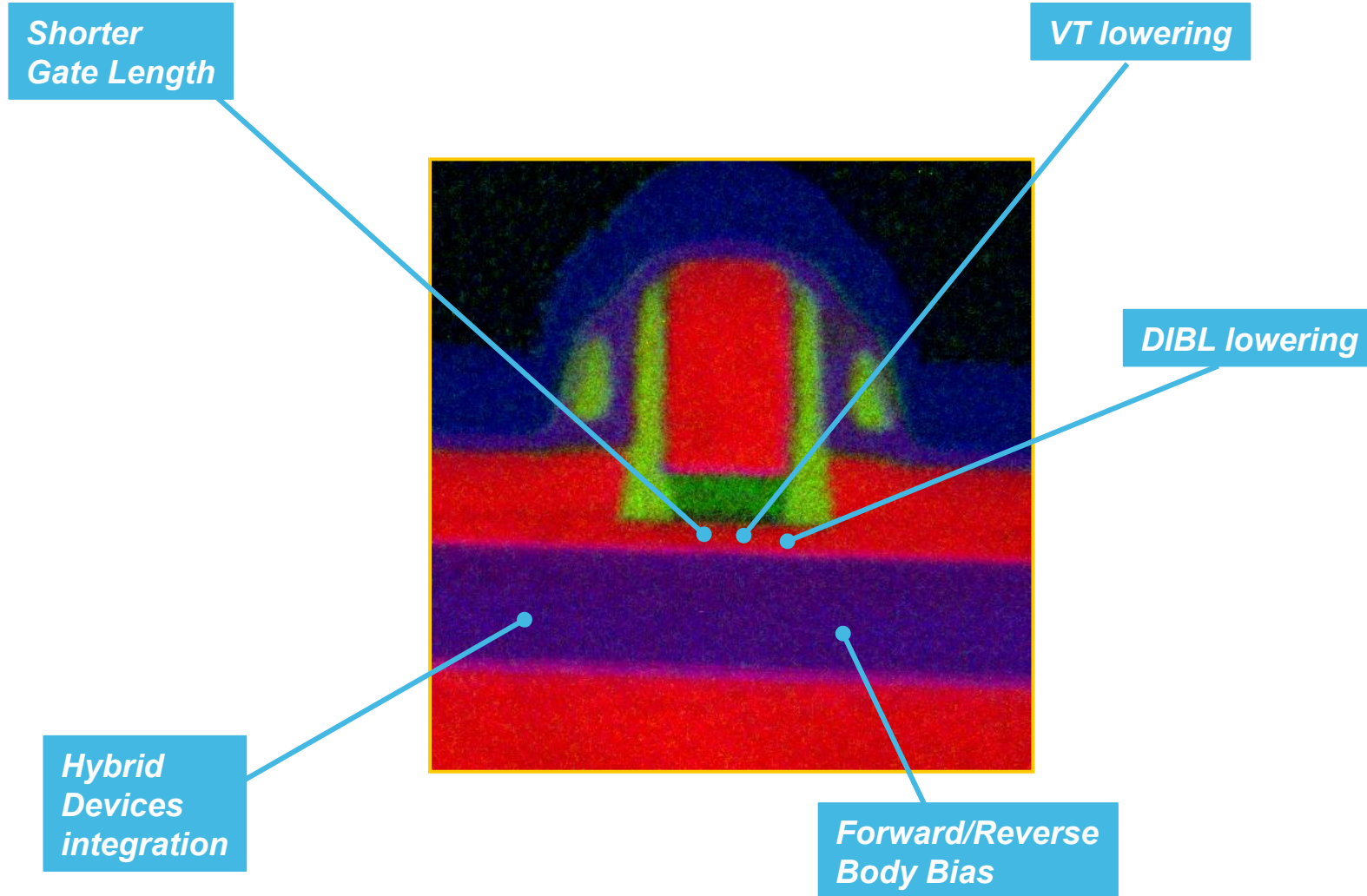
# Fully Depleted Transistors



FinFET and UTBB SOI look like one another: just a rotation  
Ultimately they converge to the same structure when scaling BOX to TOX

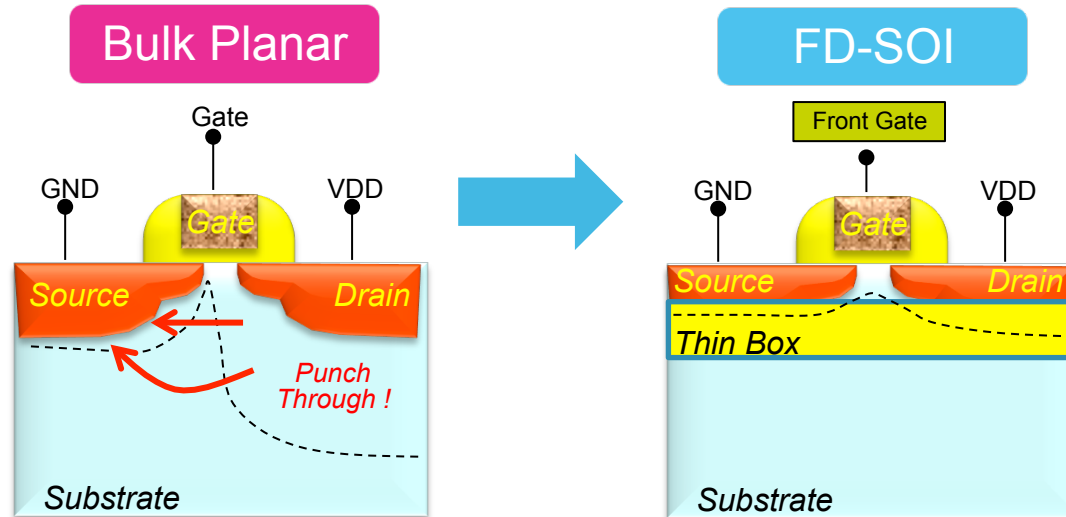


# FD-SOI Transistor Summary



# FD-SOI Electrostatics

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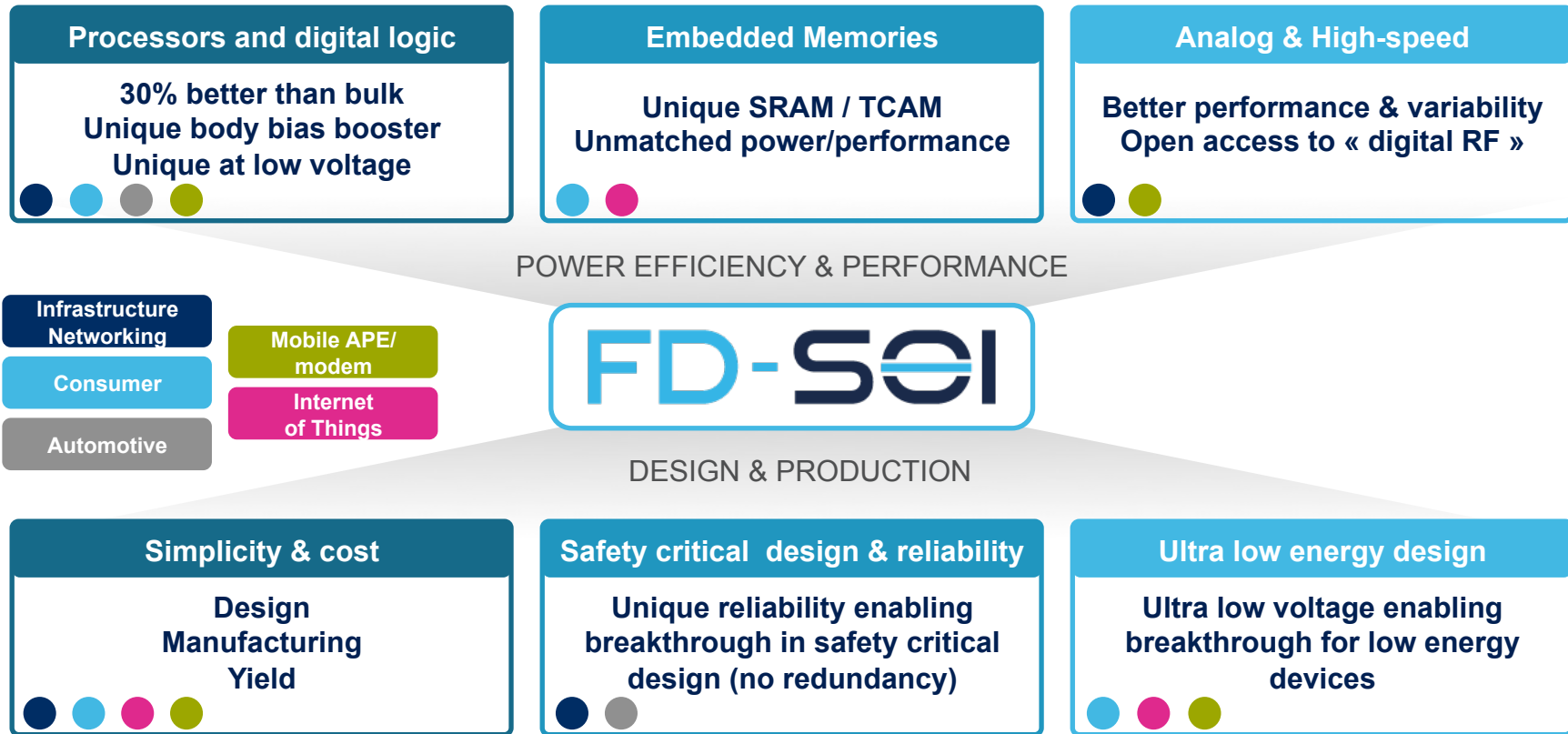
**Bulk**  $\rightarrow$   $DIBL = 0.8 \frac{\epsilon_{Si}}{\epsilon_{ox}} \left( 1 + \frac{X_j^2}{L_{el}^2} \right) \frac{T_{ox}}{L_{el}} \frac{T_{dep}}{L_{el}} V_{ds}$

**FD-SOI**  $\rightarrow$   $DIBL = 0.8 \frac{\epsilon_{Si}}{\epsilon_{ox}} \left( 1 + \frac{T_{Si}^2}{L_{el}^2} \right) \frac{T_{ox}}{L_{el}} \frac{T_{Si}}{L_{el}} V_{ds}$

Si film thickness replace junction depth ( $X_j$ )

- Short Channel effects controlled by the Silicon Film thickness
- DIBL reduced  $\rightarrow$  for same  $I_{off}$  :  $V_{tlin}$  is lower,  $I_{eff}$  is higher

# FD-SOI: unique value proposition



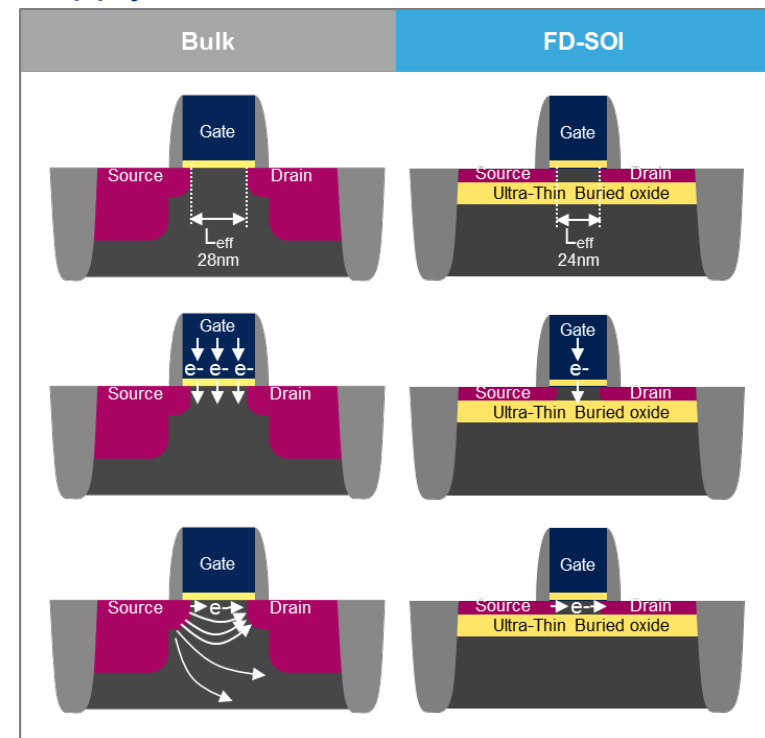


# FD-SOI Technology Benefits

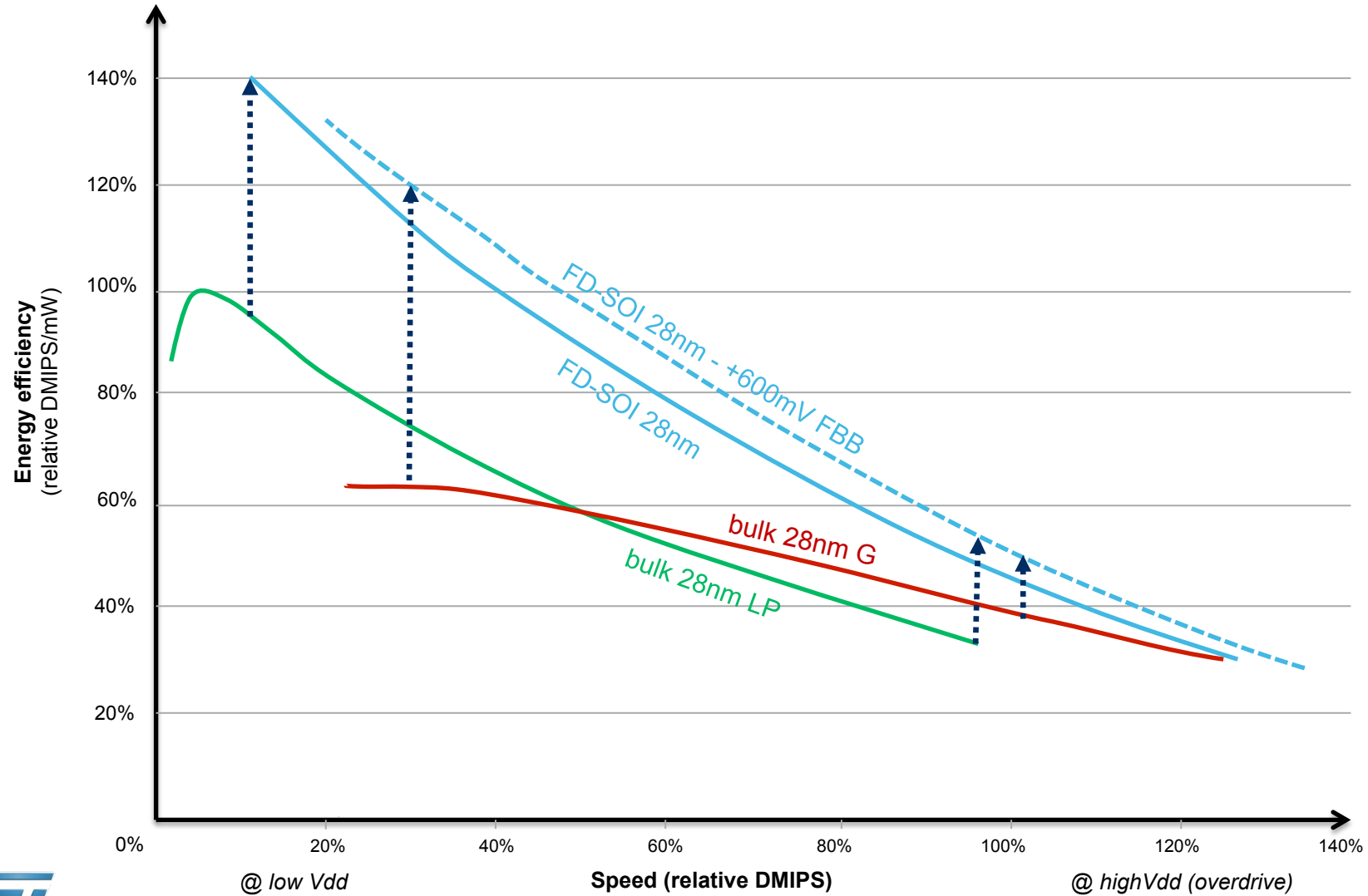
# Efficient FD-SOI Transistors

13

- FD-SOI enables better transistor electrostatics
  - Enabling faster operation at low voltage, leading to better energy efficiency
  - Improving transistor behavior, especially at low supply, enabling ultra-low-voltage operation
  - Reducing transistor variability sources
- FD-SOI has a shorter channel length
  - Confirming scalability of the technology
- FD-SOI has lower leakage current
  - Lower channel leakage current
    - Carriers efficiently confined from source to drain
  - Thicker gate dielectrics, leading to lower gate leakage
  - Enabling ultra low power SRAM memories
  - Leakage current is less sensitive to temperature with FD-SOI



# 28nm FD-SOI Best in class efficiency

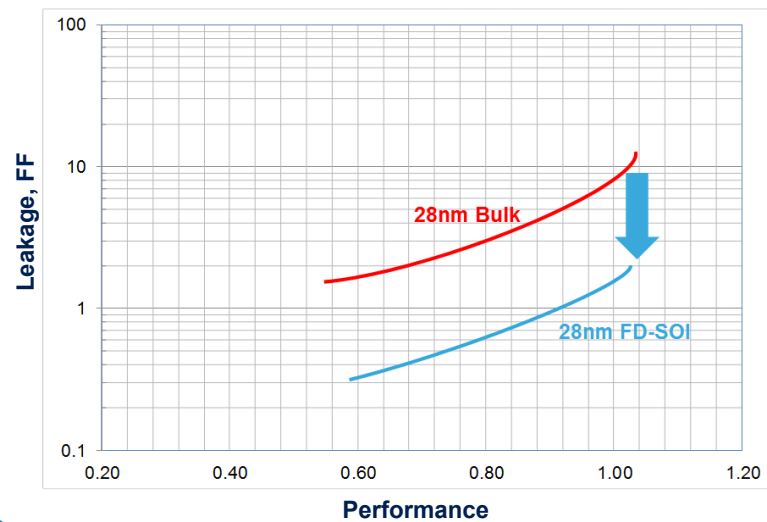


# FD-SOI – Efficiency at all levels

15

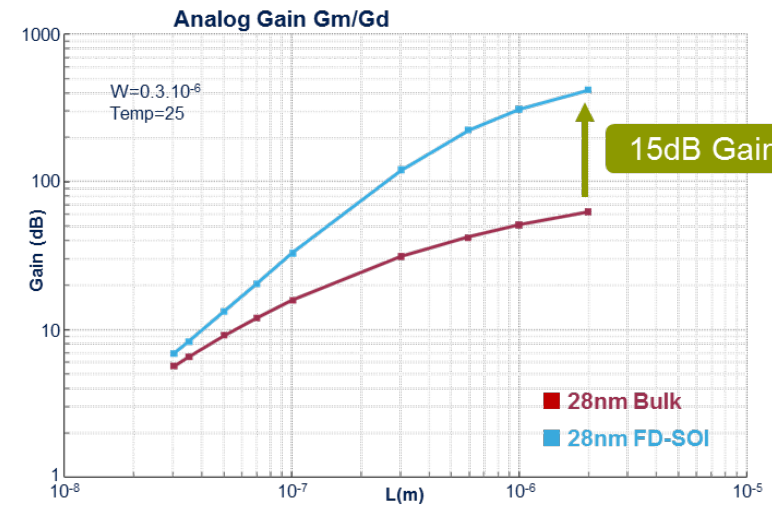
## Memories

- Similar performance with huge ~5X less leakage in 28 FD-SOI vs. Bulk
- Very low neutron-SER SRAM, 100× better than bulk
- Alpha quasi-immunity → cost savings for packaging



## Analog & High-speed

- FD-SOI analog performance far exceeds Bulk
- New design opportunity by controlling analog device characteristics through body biasing techniques

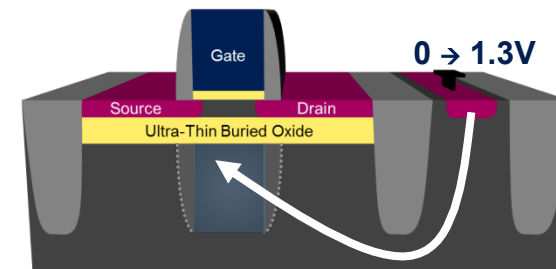


# Forward Body Biasing (FBB)

16

A very reasonable effort for extremely worthwhile benefits

- An **extremely powerful** and flexible concept in FD-SOI to :
  - Boost performance
  - Optimize passive and dynamic power consumption
  - Cancel out process variations and extract optimal behavior from all parts

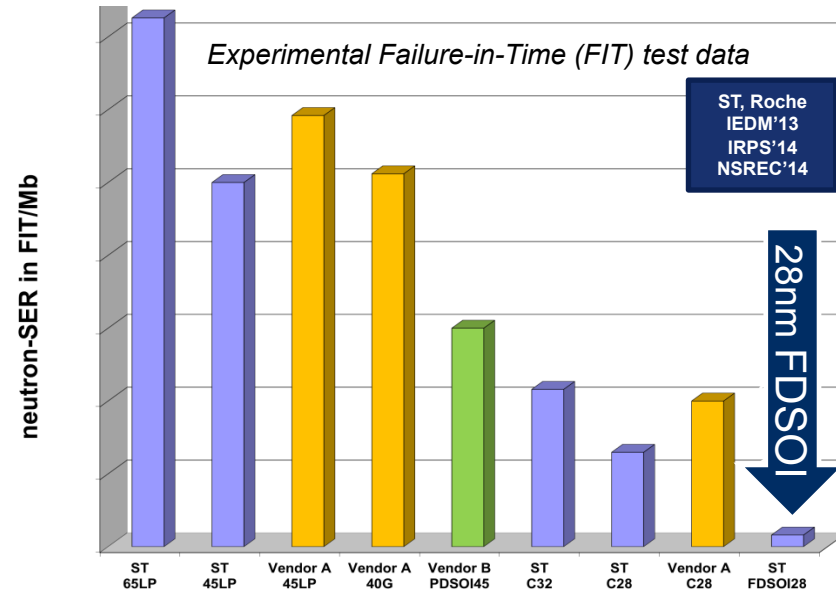


- Comparatively **easy to implement** – if you've ever done DVFS you'll have no difficulty with Body Biasing



# Best SER (Soft Error Rate) with FD-SOI

- Very low neutron-SER <10 FIT/Mb
  - ECC-SRAM not systematically required
  - standard FF intrinsically robust <10 FIT/MFF
  - rad-hard FF libraries available = 0 FIT
- Single Event Latchup immunity
  - tested with space ions 125°C/1.3V
- Alpha quasi-immunity <1 FIT/Mb
  - no need for ultra-pure alpha packaging
- Very small error clusters: 99% single bits
  - Single Error Correction efficient/sufficient
  - no need for bit scrambling as for BULK

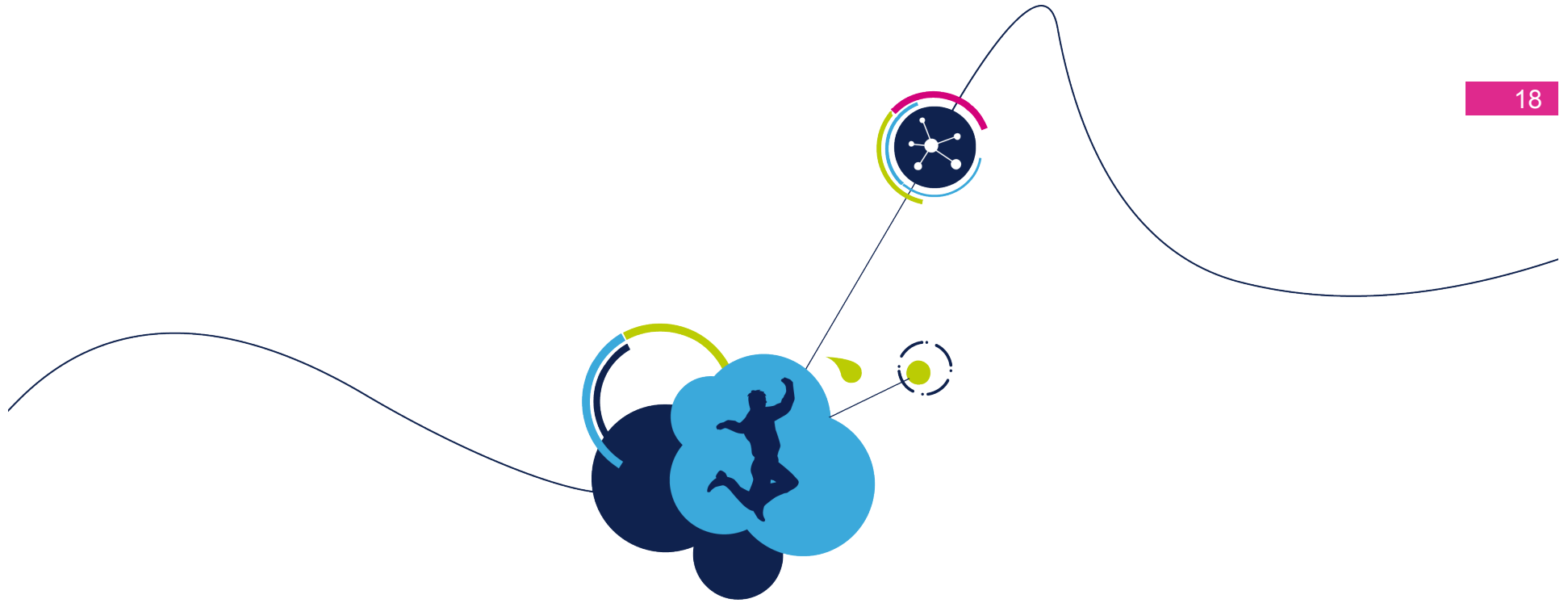


Gain w.r.t. BULK	UTBB FDSOI	FinFET
Alpha	<b>1000×</b>	<b>15×</b>
Neutron	<b>100×</b>	<b>10×</b>
Latchup	<b>immune</b>	<b>not reported</b>
Multiple Cell Upsets	<b>99% single bit</b> max. 2 cells	<b>max. 4 cells</b> worse according to INTEL

ST, Roche, CISCO SER workshop, Oct'14

TSMC, Fang, CISCO SER workshop, Oct'14



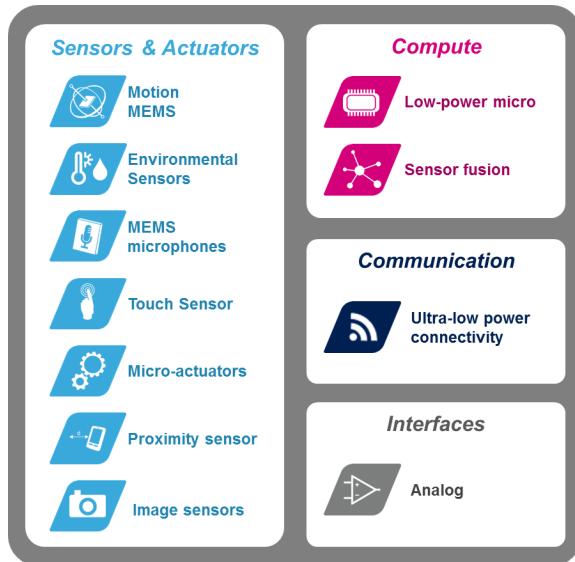
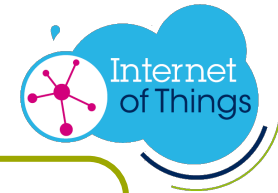


# FD-SOI Benefits

## Application Examples

# FD-SOI benefits for Internet of Things

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### FD-SOI benefits for IoT

- Ultra low voltage / sub-threshold
- Low cost
- Integration RF/connectivity, micro, power management



Smart Car



Smart Home



Smart Me  
Health / wellness



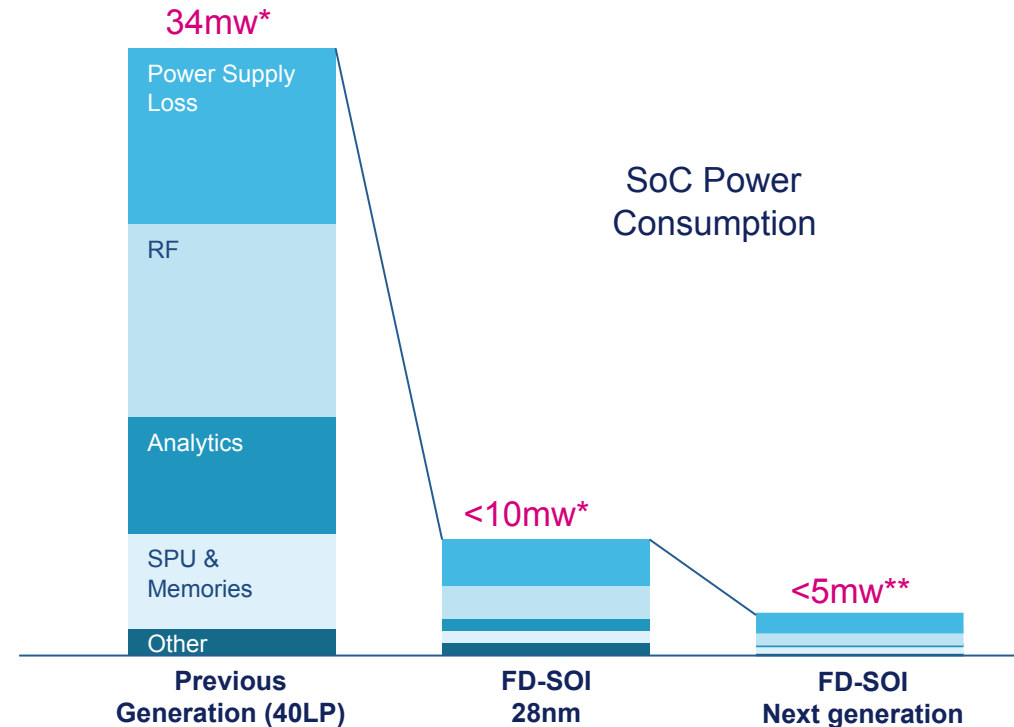
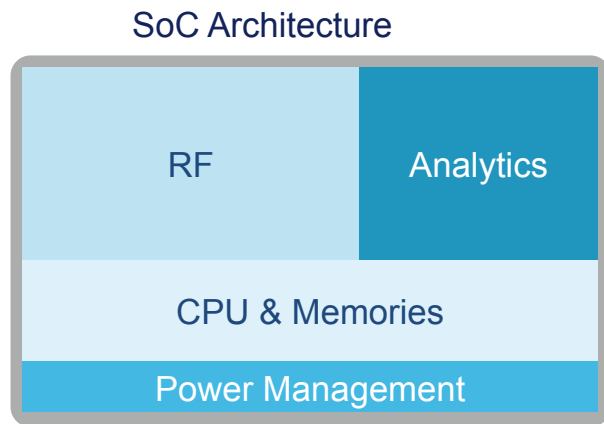
Smart City



Smart Industrial

# Example: Ultra Low Power in IoT

20



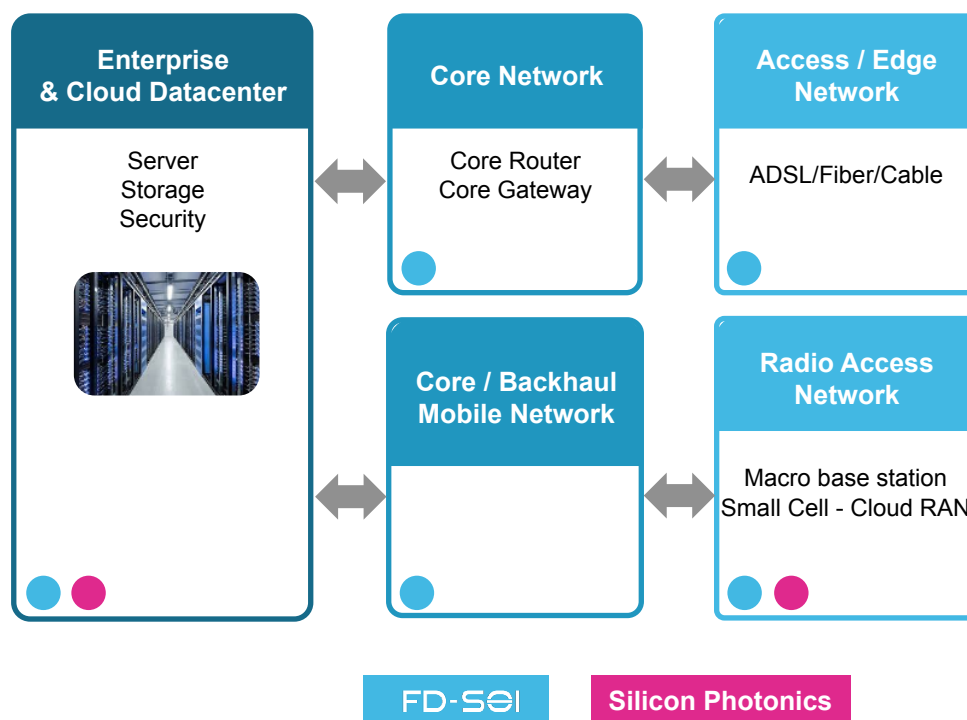
X3 to X6 Power Consumption Improvement with FD-SOI

\* Measured on Silicon / Product Simulation

\*\* Projection

# FD-SOI benefits in network infrastructure

21

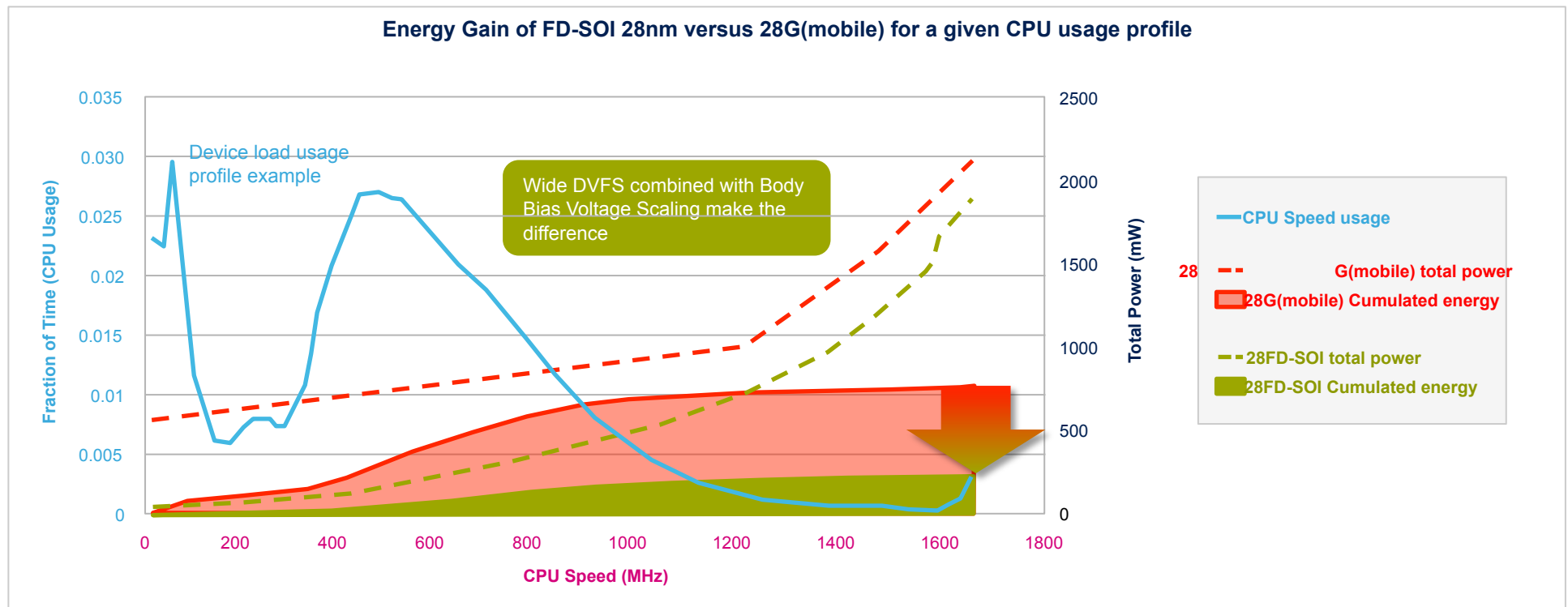


## FD-SOI benefits

- Power efficiency
- Adapt power consumption to load
- Design complexity similar to previous nodes
- Applicable to all network infrastructure products
- Scalable down to FD-SOI 14nm

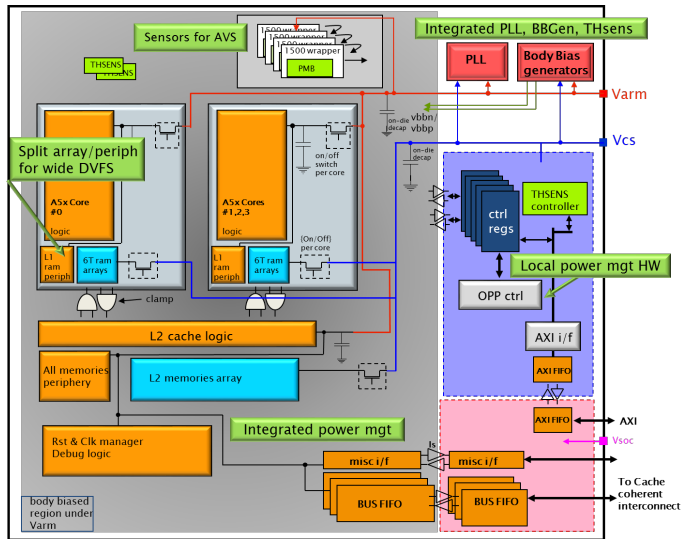
# Example: Power efficiency in Mobile Infrastructure

22

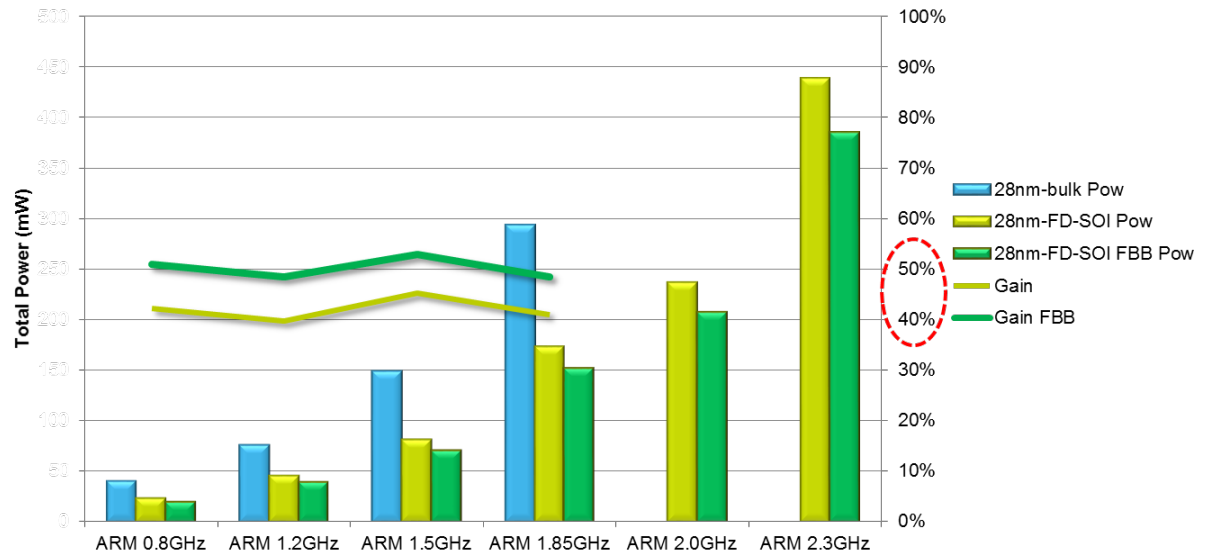


FD-SOI : up to 70% better energy consumption vs. 28nm bulk

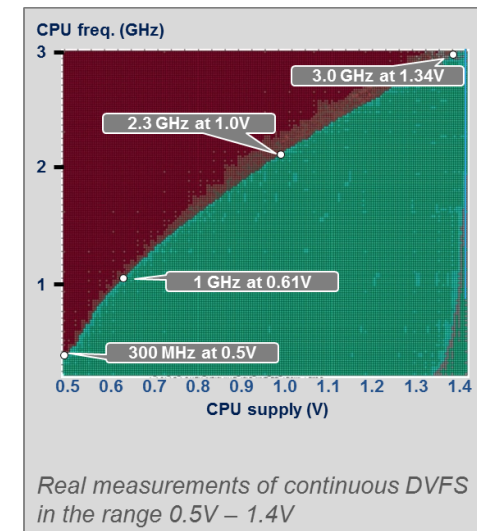
# Example: Power efficiency in APUs



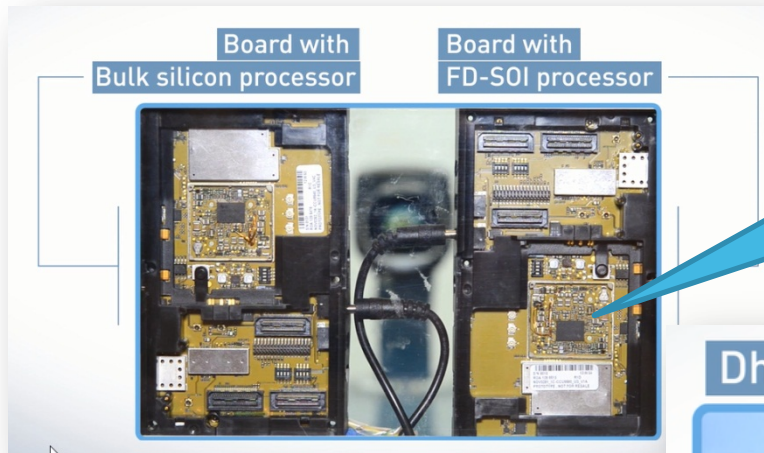
A9 Single Dhrystone power consumption



- FD-SOI allows the widest Vdd range for voltage scaling
- Still guaranteeing top notch speeds at very low operating voltage
- DVFS energy efficiency optimization is further extended thanks to body bias
  - Allowing to balance and optimize the static and dynamic power consumption components

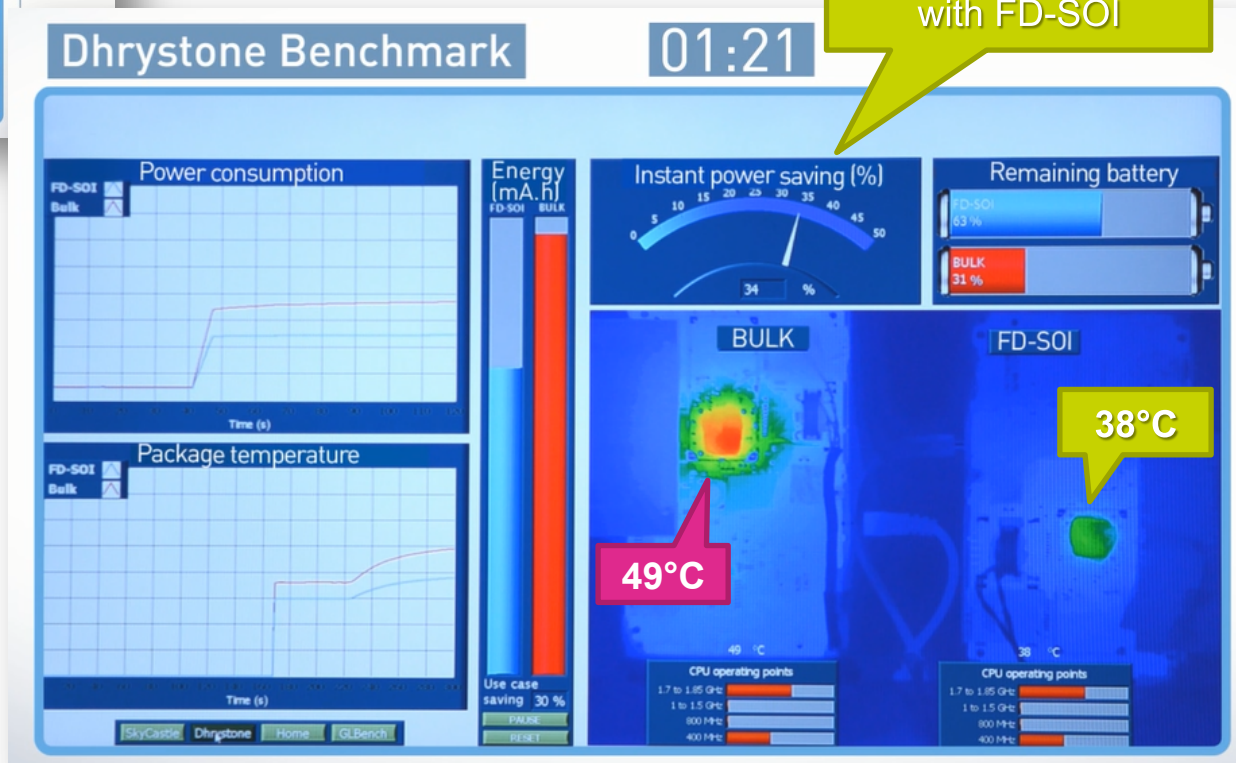


# APU Cooler Demo: Si evidence



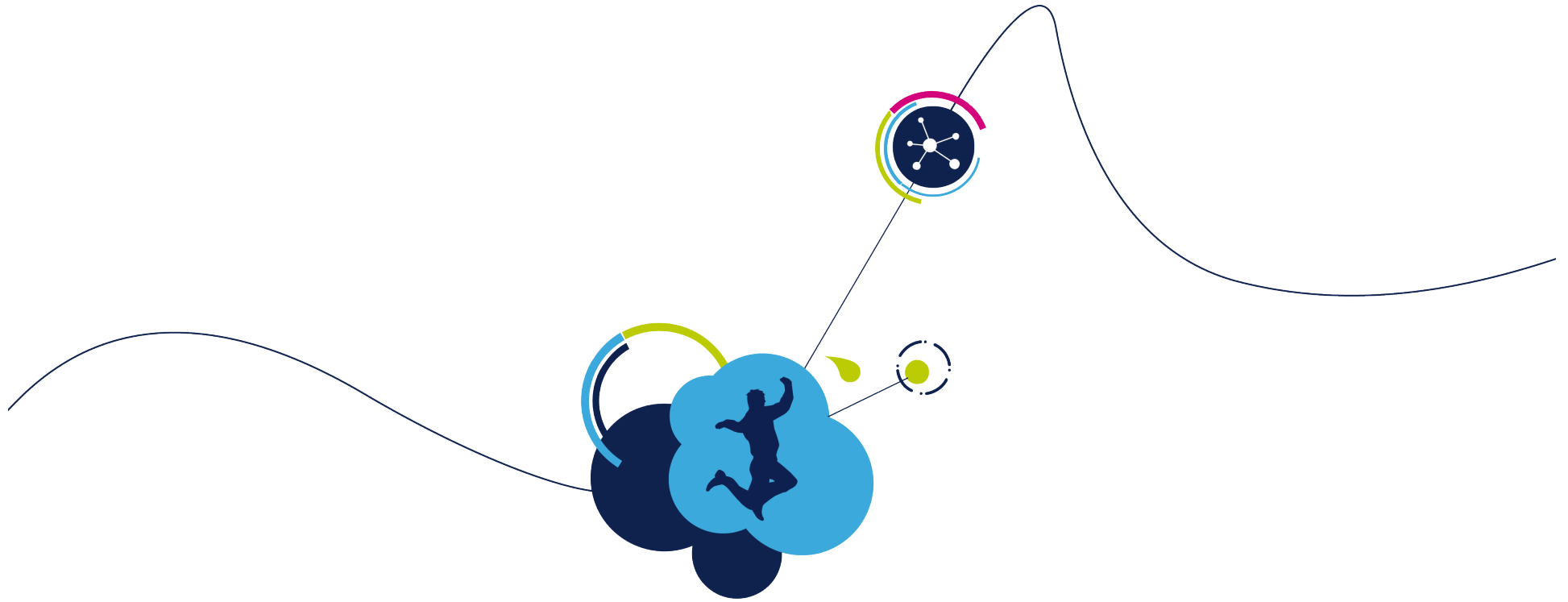
Same APU surface (28LP HKMG & 28nm FD-SOI) running Dhrystone bench at same 1.85GHz frequency

35% less total power with FD-SOI



At same speed, 28FD-SOI is 11° C less than 28nm bulk.





# FD-SOI: The Body Bias benefit

# How to improve Energy Efficiency?

26

- Several technics exists but bulk process limit their efficiency in advanced nodes (28/14nm)

Technique	Limitations in Bulk
<b>Increasing the # of processing cores</b>	<ul style="list-style-type: none"><li>• leakage current for a given performance</li><li>• limited DVFS</li></ul>
<b>Wide range DVFS</b>	<ul style="list-style-type: none"><li>• [Vmin, Vmax] range is limited by variability</li><li>• Performance degradation when supply V reduces</li><li>• Memory Array minimum voltage</li></ul>
<b>Dynamic transistor Vt control</b>	<ul style="list-style-type: none"><li>• limited body bias range</li><li>• limited benefit in 28 nm / no benefit beyond</li></ul>
<b>Poly biasing of the transistors</b>	<ul style="list-style-type: none"><li>• limited poly biasing range</li></ul>

- New process & design technics are needed

# FD-SOI: The FBB advantage

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- What is Body Biasing?

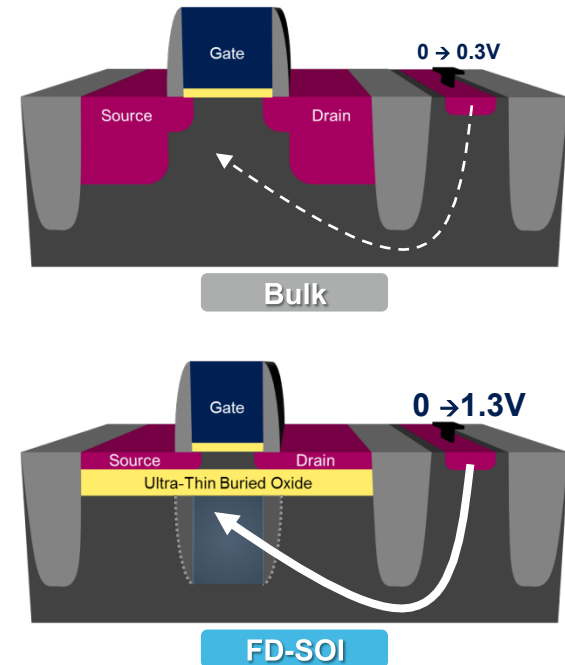
- A voltage is applied to the substrate (or body).
- When voltage is positive, it is called **Forward Body Biasing**, or **FBB**

- Why FBB is much more efficient in FD-SOI?

- The Insulator layer (UTTB) prevents the parasitic effects that normally appear during the body biasing
- This allows much wider range of biasing compared to Bulk
- FBB can be modulated dynamically during the transistor operation and the transitions are transparent to the SW

- FBB benefits

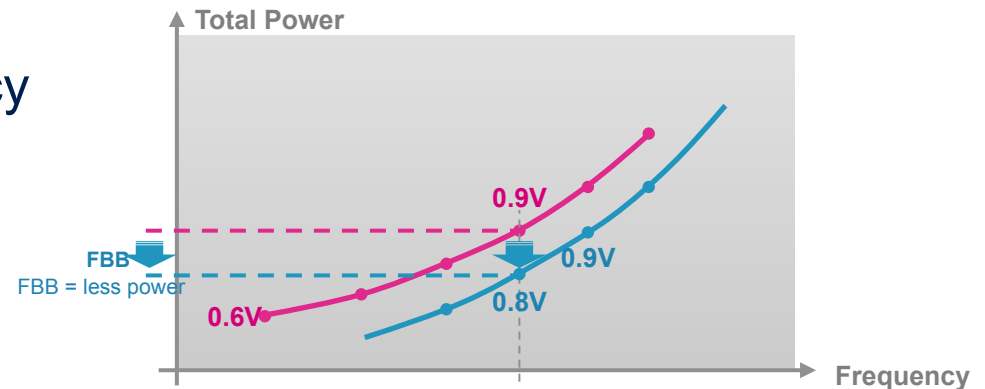
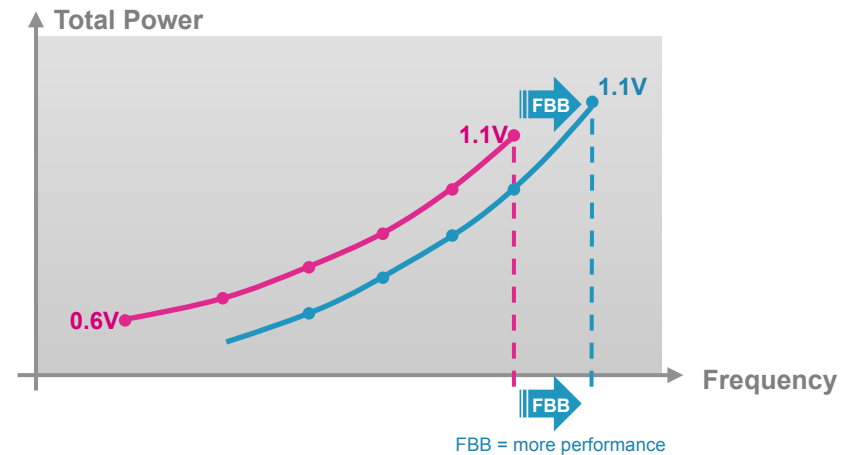
- **Performance boost**
- **Reduce power consumption** at a given performance requirement
- **Process compensation** reducing the margins to be taken at design
- **Easy to implement:** seamless inclusion in the EDA flow



# FBB for performance boost and power efficiency

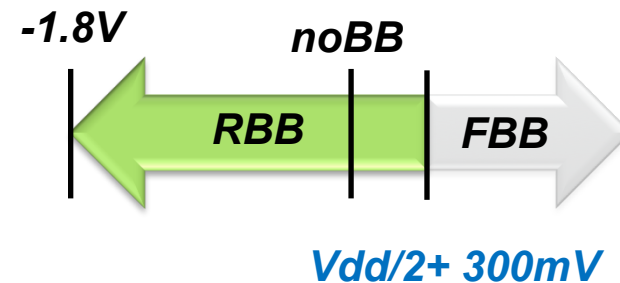
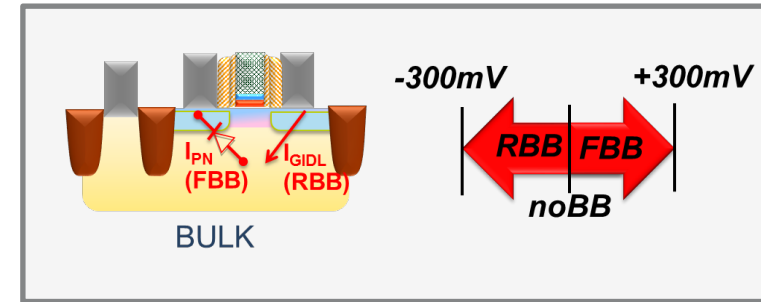
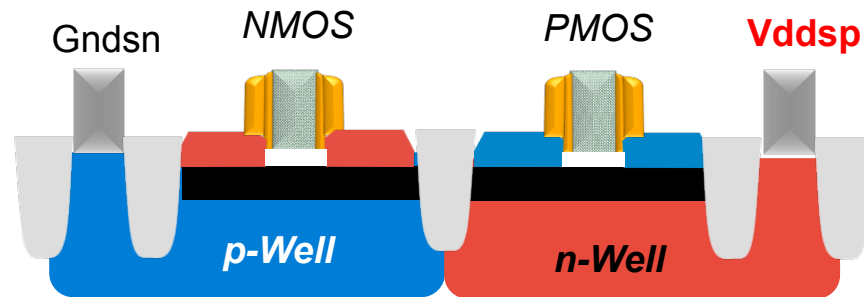
28

- FBB provides performance boost when voltage can't be increased
  - Limited impact on dynamic power, no impact on voltage drops
  - → More efficient performance increase than turning the voltage
  - Impact on leakage at high temperature
  - Back into 28G range but leakage can be turned off anytime by removing FBB
- FBB improve the power efficiency at a given frequency
  - Limited impact on leakage, slightly higher than without FBB
  - Drastically decrease dynamic power

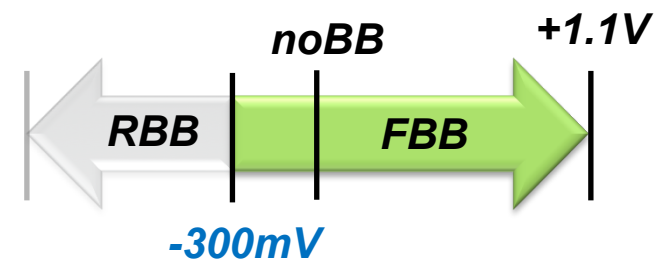
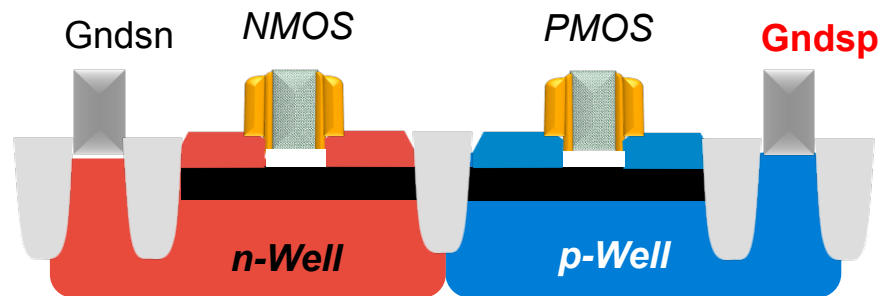


# FD-SOI: LVT & RVT Body Bias range

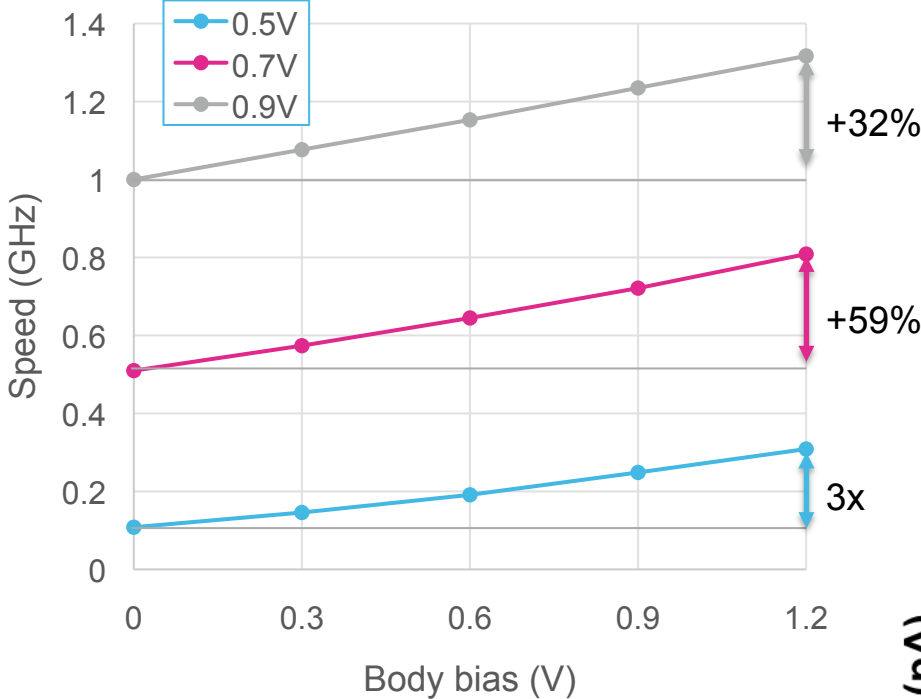
## RVT : Conventional Well (CW) - RBB



## LVT : Flip Well (FW) - FBB

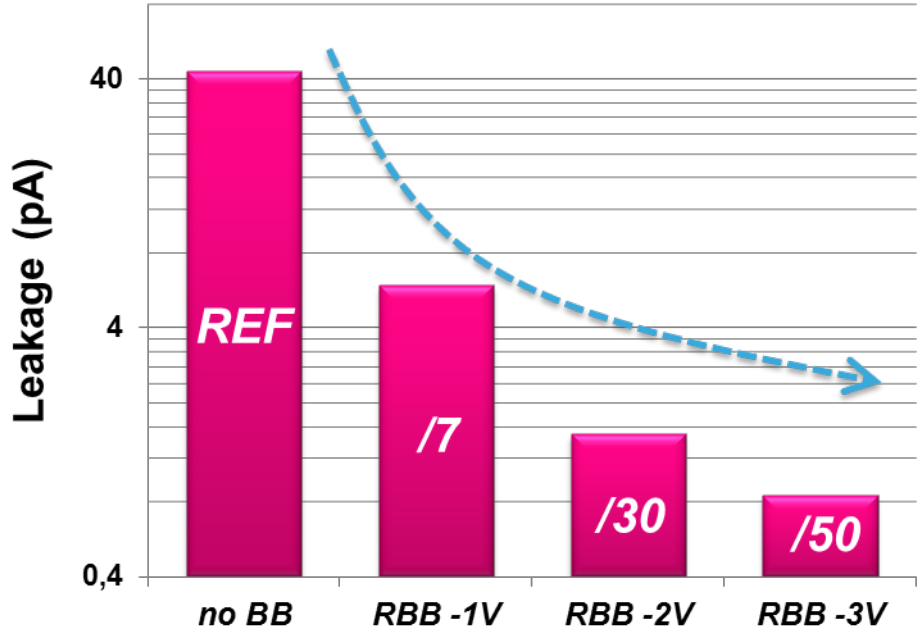


# Body Bias Efficiency



LVT / Forward Body Bias

RVT / Reverse Body Bias

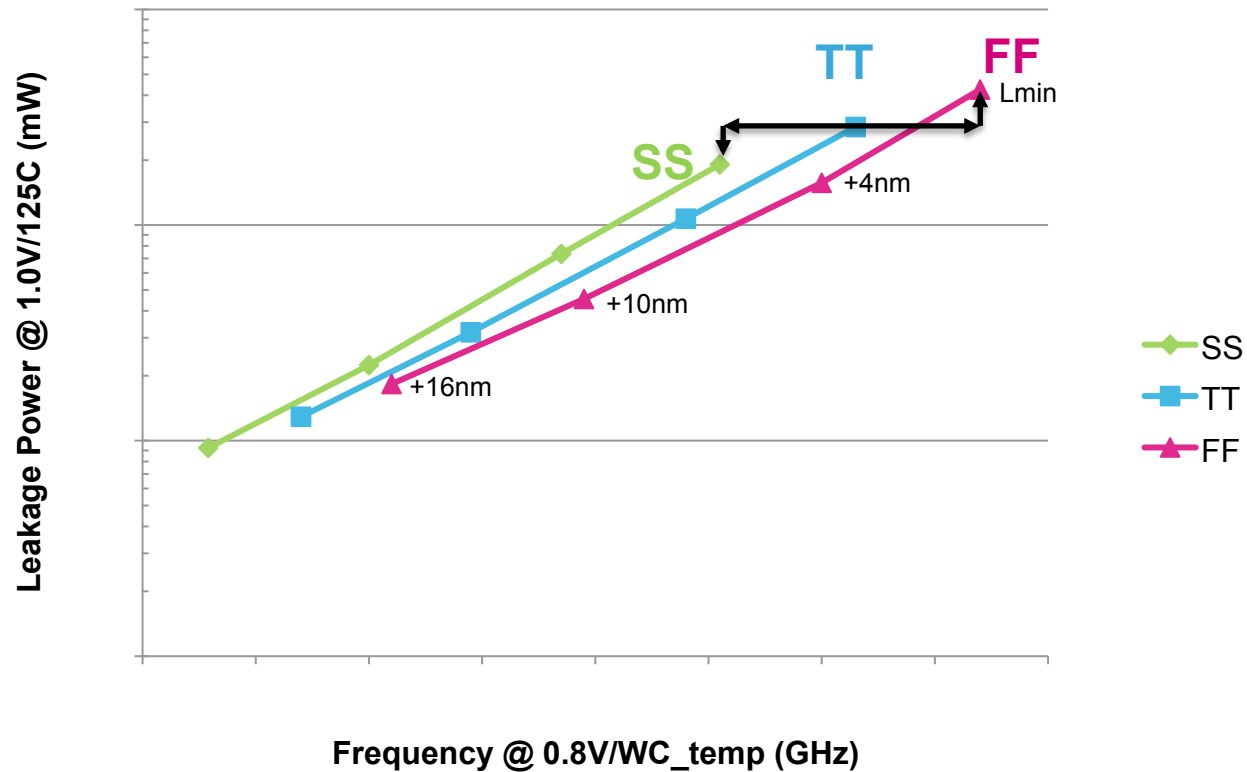




# Process Compensation with Forward Body Bias (FBB)

# Performance Corner Spread w/o Body Bias

32

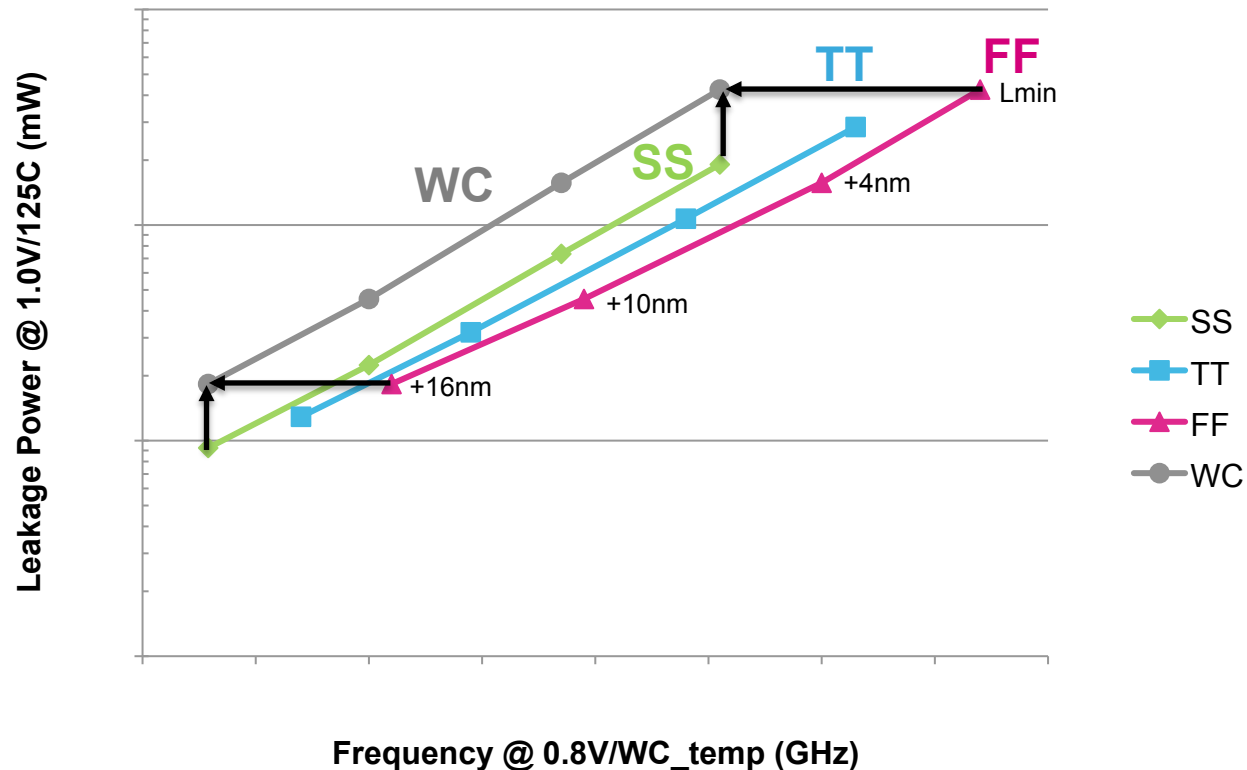


- Frequency and leakage corner spreads depend on PVT and channel length



# Worst Case Performances w/o Body Bias

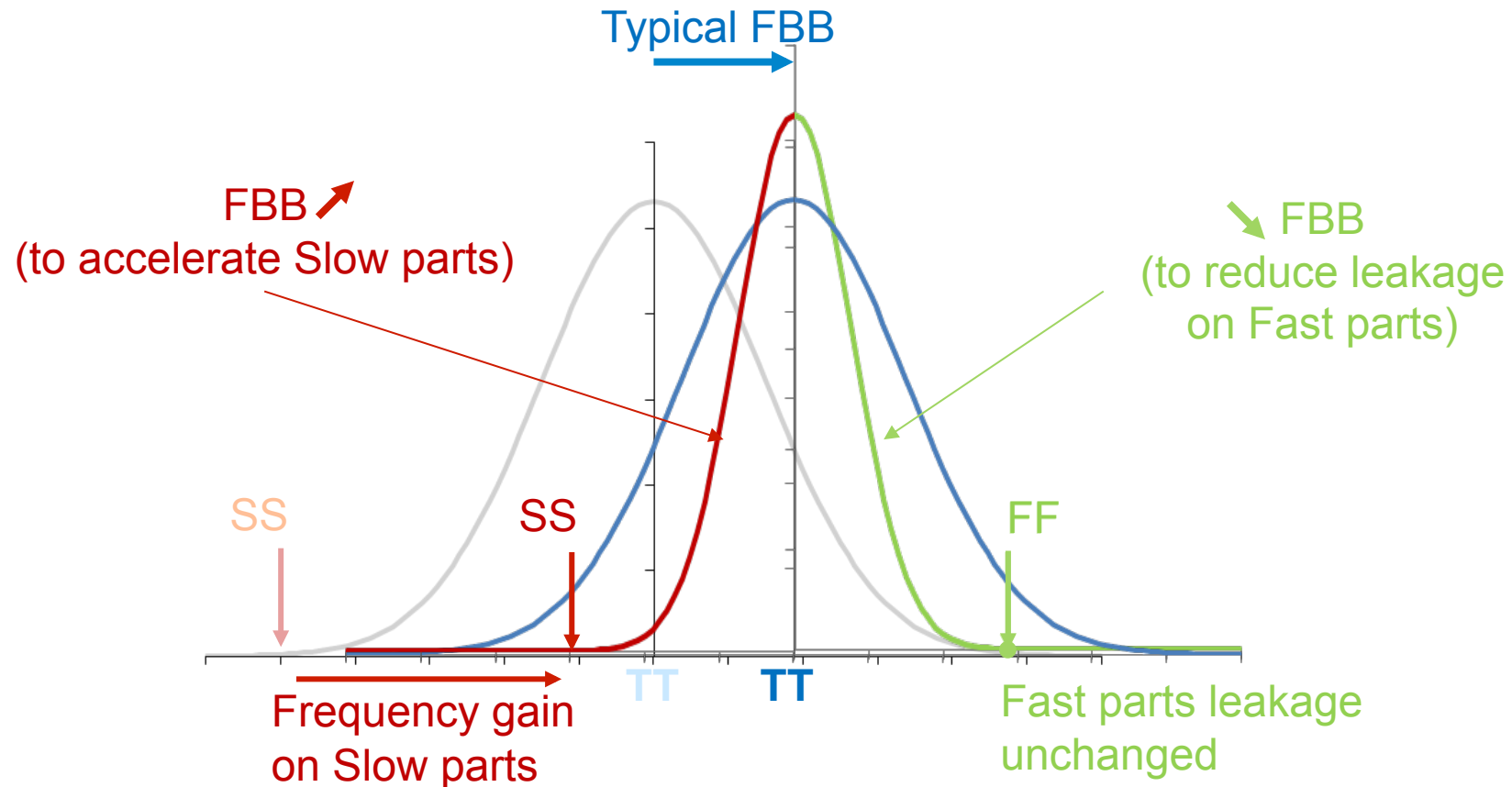
33



- For each gate length, the worst case performance trend (WC) is built using the slowest case (SS) and the leakiest case (FF)
- This is what used for ASIC sign-off

# FBB-based Process Compensation: Principle

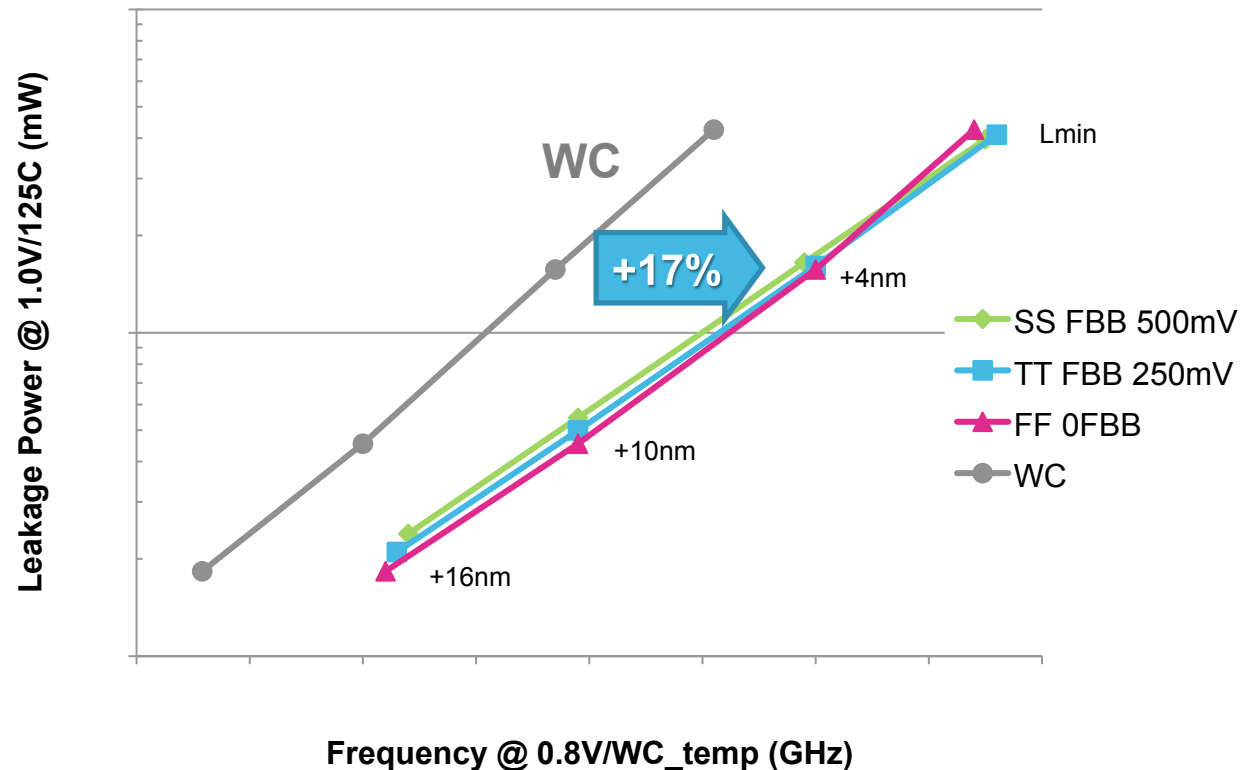
34



- SLVT doesn't allow RBB → FBB must be applied on typical to allow “pseudo-RBB” for Fast parts (leakage containment)
- Higher FBB is applied to accelerate Slow parts

# Process Compensation Through FBB

35



- Process Compensation through FBB allows
  - Masking SS-FF process spread
  - Recovering +17% speed in 28nm FD-SOI, at no dynamic power expense (as it would happen if using AVS)

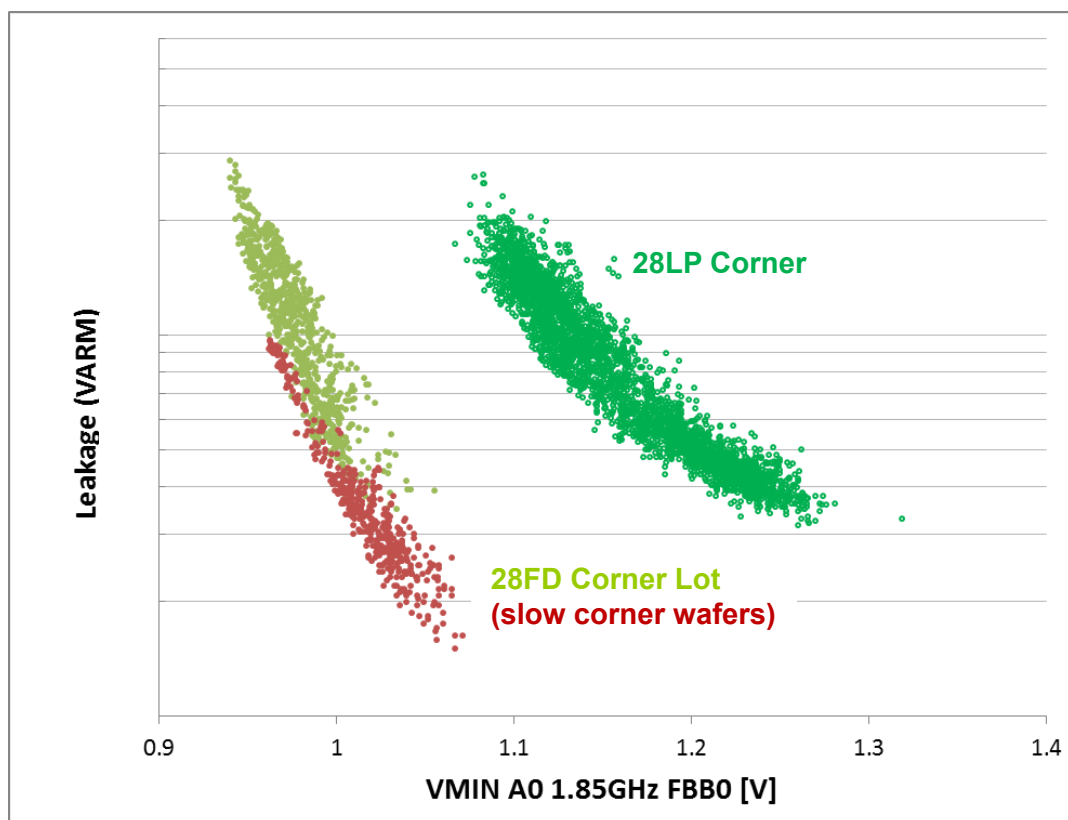
# FBB: a “true” process compensation

36

- AVS (Adaptive Voltage Scaling) compensates global process variations adapting the supply voltage
- FBB acts on transistor  $V_t$ , allowing a “true” process compensation
  - Allowing asymmetric compensation of Nmos and Pmos
  - Allowing easy different compensations by block
    - Large SoC may be partitioned, each one having its own compensation
      - Managing multiple BB generators is easier than multiple supply voltages
- FBB enables advanced compensation techniques (R&D)
  - Temperature tracking & compensation
  - BTI (aging) compensation

# Cortex A9™ Benchmark 28nm Silicon Results

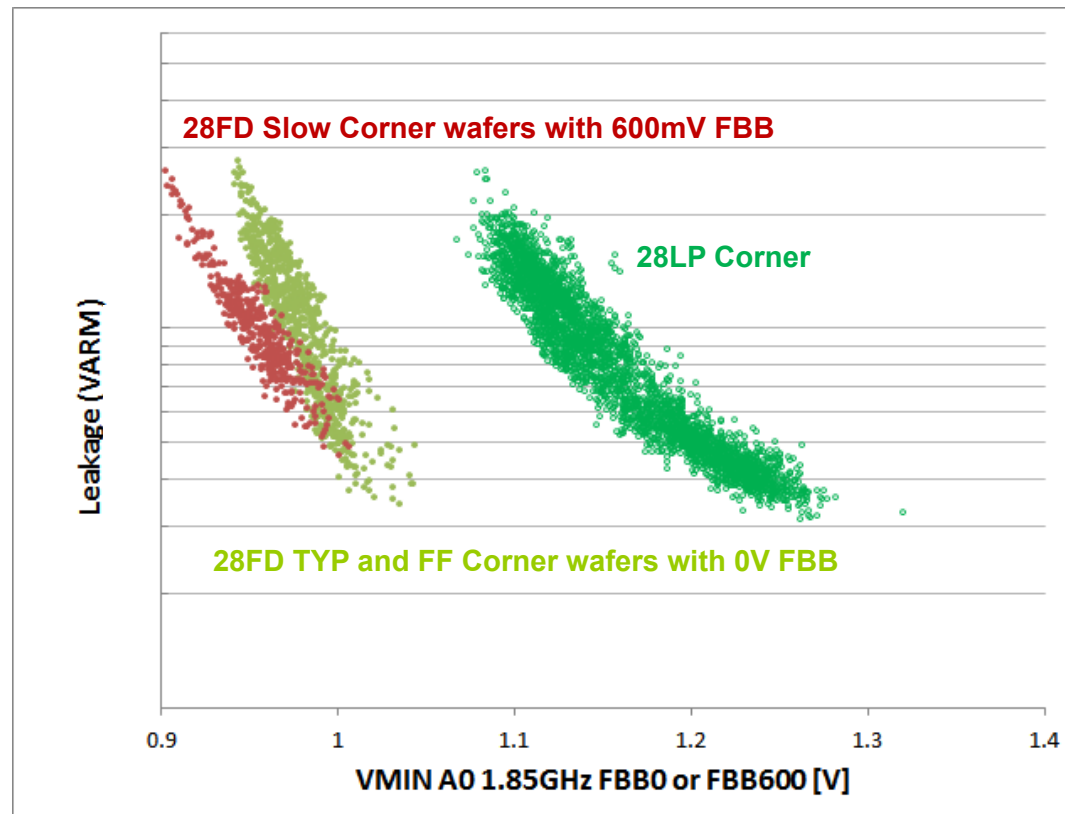
37



- VMIN for a given frequency (1.85GHz)
  - Vmin search is an EWS metric for Fmax
  - The metric allows a one-to-one benchmark between 28FD and 28LP performances

# Cortex A9™ Benchmark Process Compensation through FBB

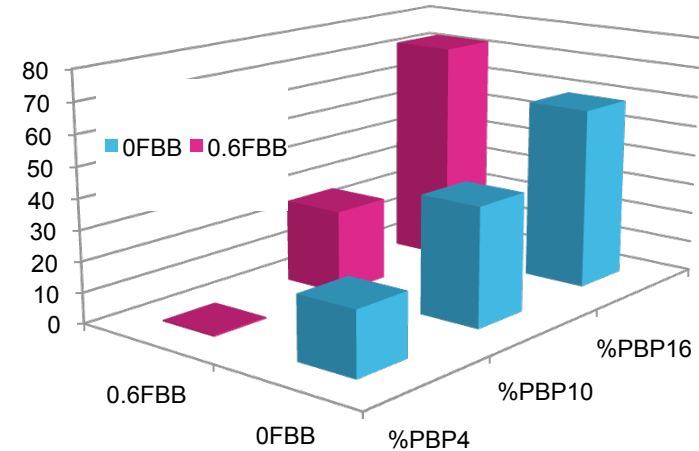
38



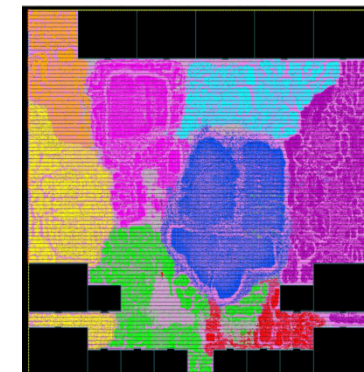
- Applying FBB 600mV enable reaching the target VMIN perfs
  - SLOW Population brought in TT-FF range

# Process compensation through FBB benefits at implementation level

- ARM Processor
  - 350 K gates, 50k FF + memories
  - Target frequency: 1GHz @ WC/0.85V
- Two FD-SOI implementations comparison
  - Standard WC methodology
  - SS corner compensated with 600mV FBB



Sign-off	Standard	With Process Compensation
Area ( $\mu\text{m}^2$ )	1	0.90x
Total Power (mW) @ Vmax, 125C, RCmax	1	0.75x
Leakage (mA) @ Vmax, 125C	1	0.7x





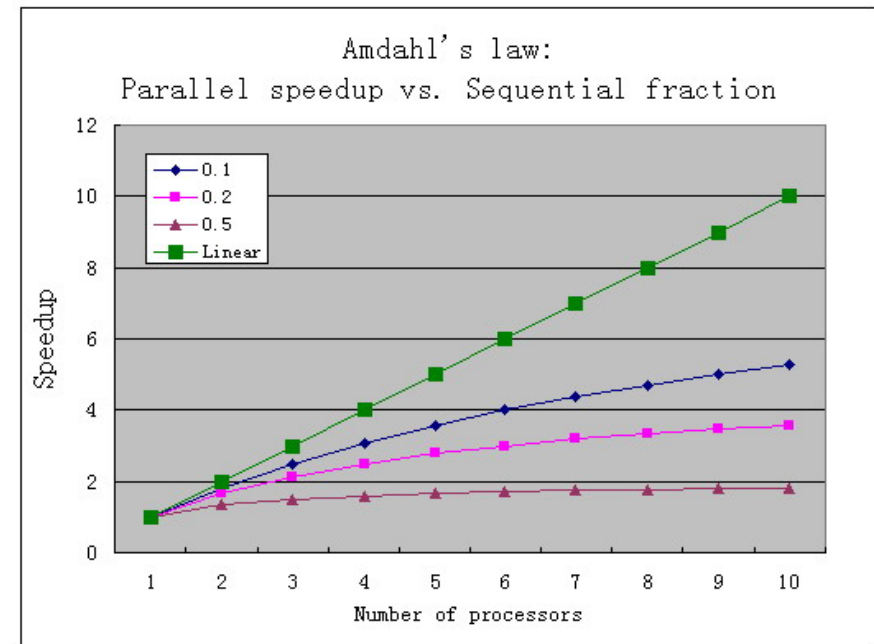
# FD-SOI & Multiprocessing



# Multicore Delivers more MIPS/mW

41

- No doubt multicore can deliver more MIPS per mW
  - Core should be implemented for best power efficiency/peak frequency trade-off
  - SoC should host as many cores as possible at every technology node
    - scalability achieved through core number increase
    - no more by frequency scaling
- Major issues
  - Amdahl's law
  - Memory hierarchy efficiency

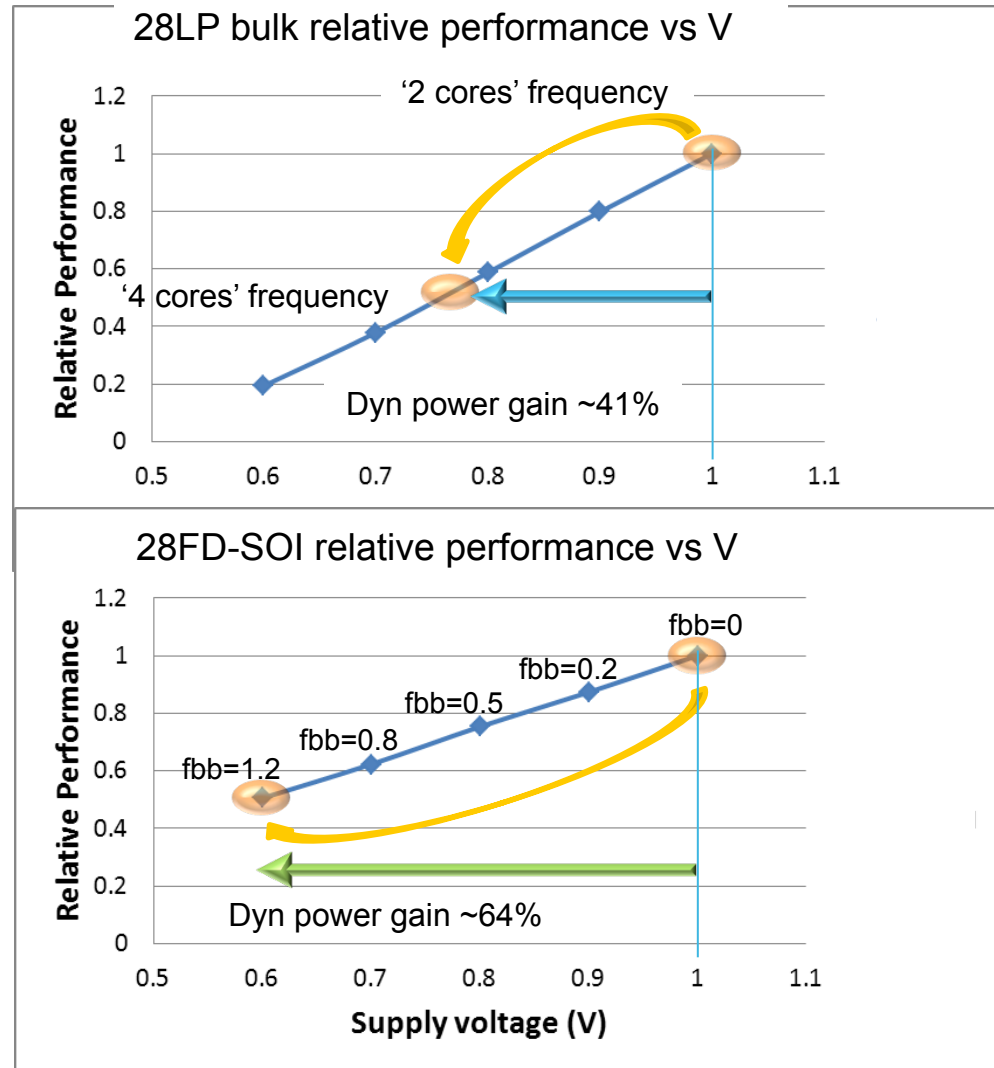


D.Jacquet et al., VLSI Symposium 2013



# Multiprocessing and wide DVFS - 1

- 2 cores vs 4 cores
  - Ideal speed up factor
  - 2 cores@F=4 cores@F/2

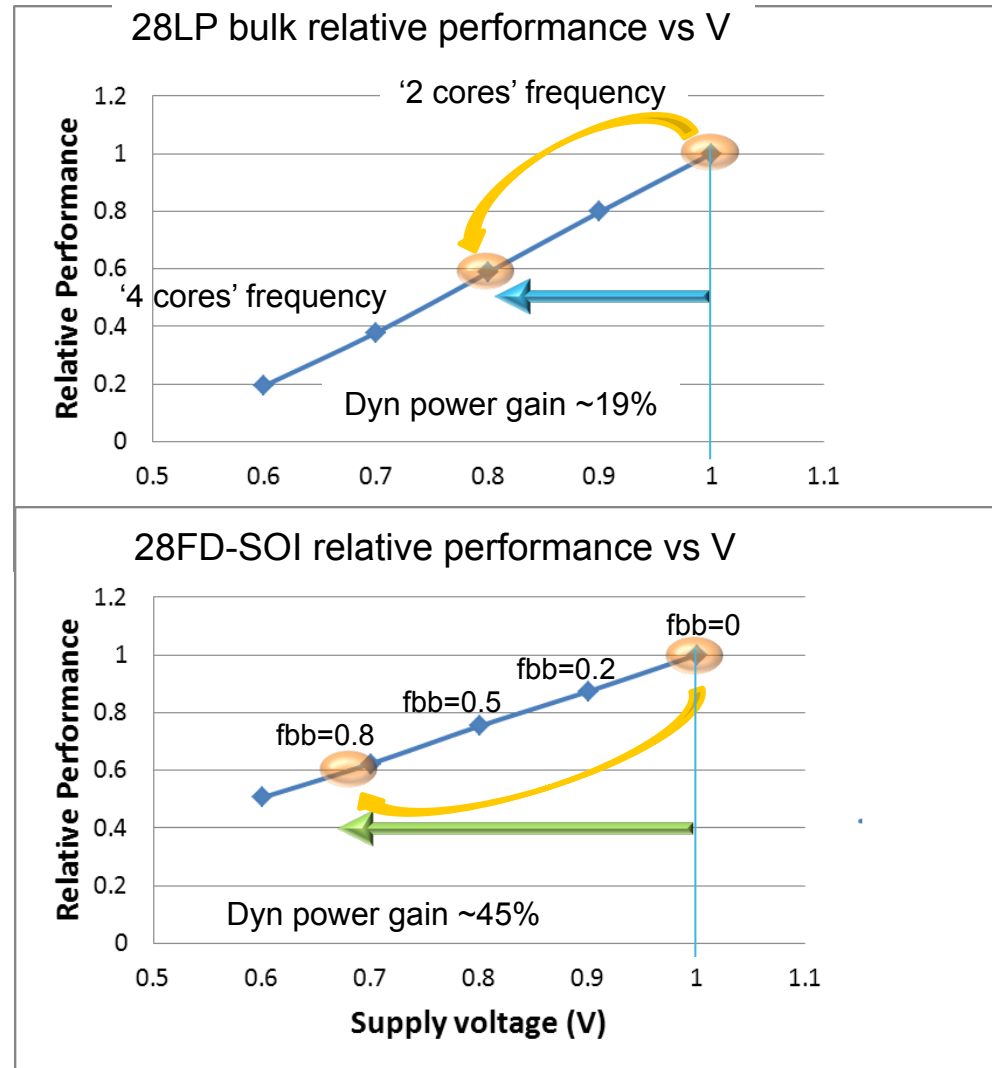


D.Jacquet et al., VLSI Symposium 2013



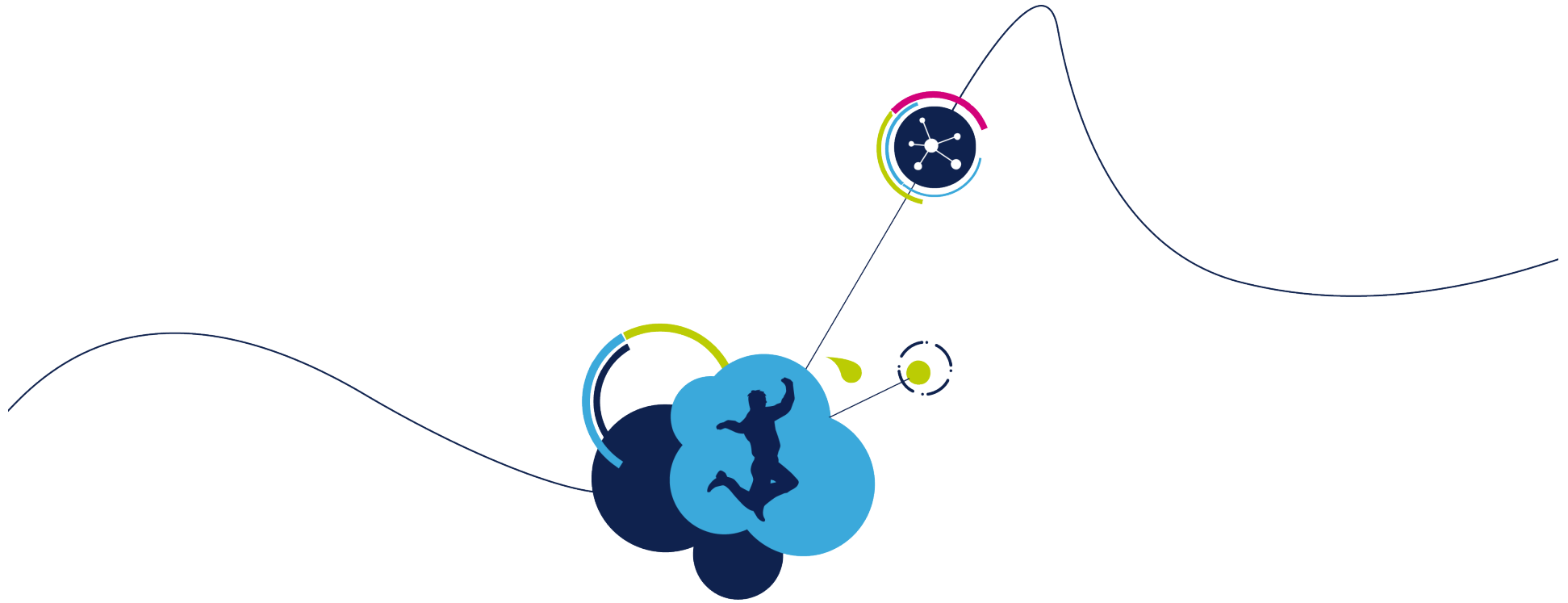
# Multiprocessing and wide DVFS - 2

- 2 cores vs 4 cores
  - Seq fraction = 0.1
  - 2 cores@F=4 cores@0.6F



D.Jacquet et al., VLSI Symposium 2013



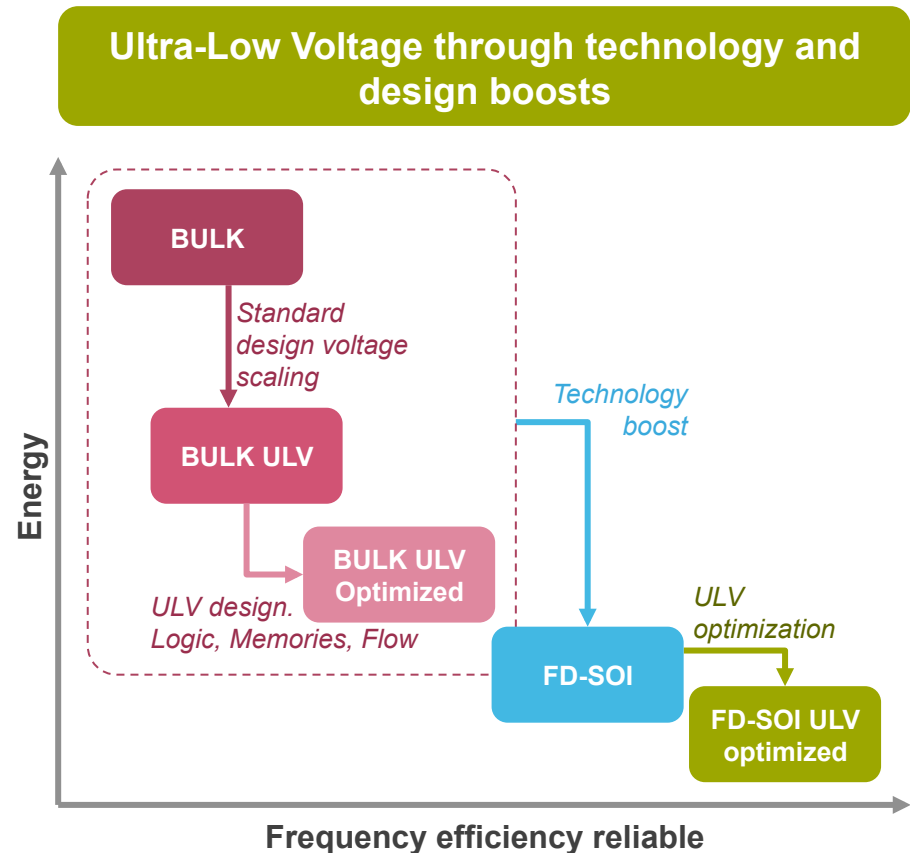


# FD-SOI and Ultra Low Power / Voltage applications

# ULV Gains Confirmed in 28 FD-SOI

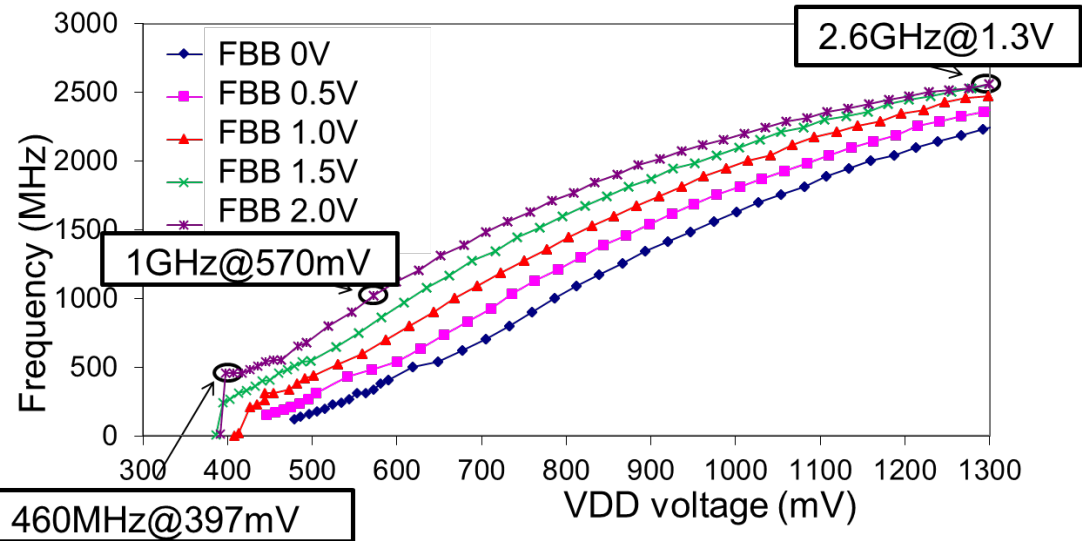
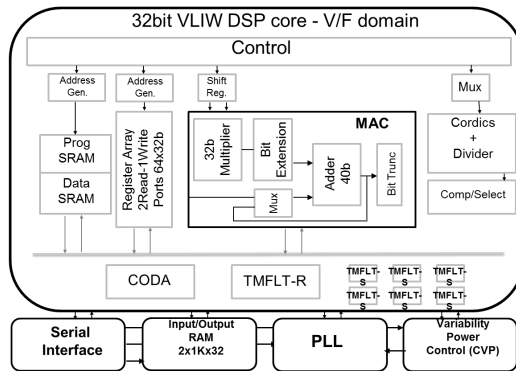
45

- Intrinsic FD-SOI advantage for ULV
  - Electrostatic control enhancement
    - speed at low voltage
  - Undoped homogeneous channel
    - Reduced variability
    - Lower minimum usable supply voltage
- Specific design solutions to leverage FDSOI outstanding performance at ULV
  - Higher  $I_{ON}$  for clock tree
  - FBB for improved energy efficiency and delay

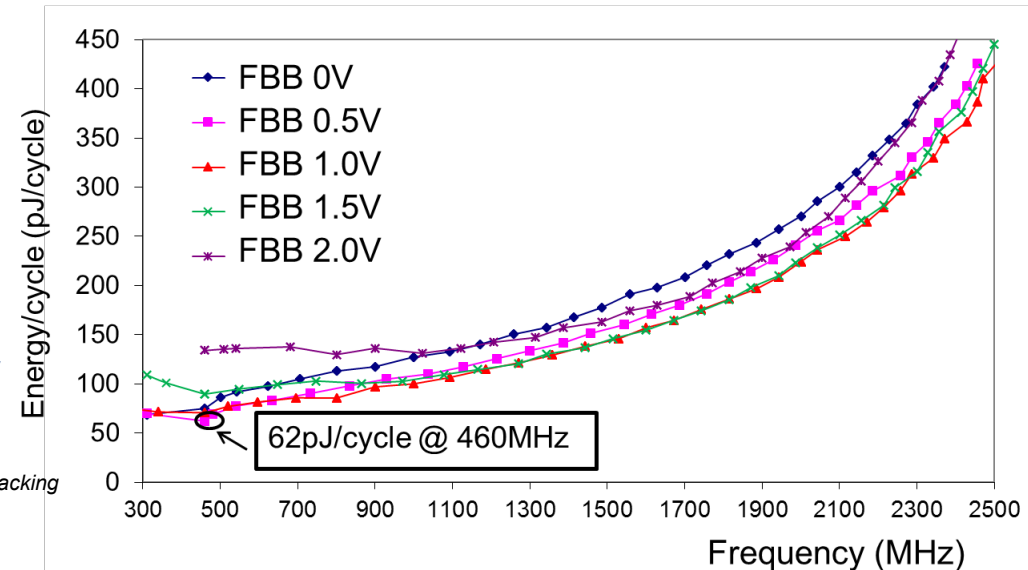


# Example: ULV DSP

- FBB up to +2V and FMAX tracking :
  - ↗ frequency up to 460MHz at minimum voltage



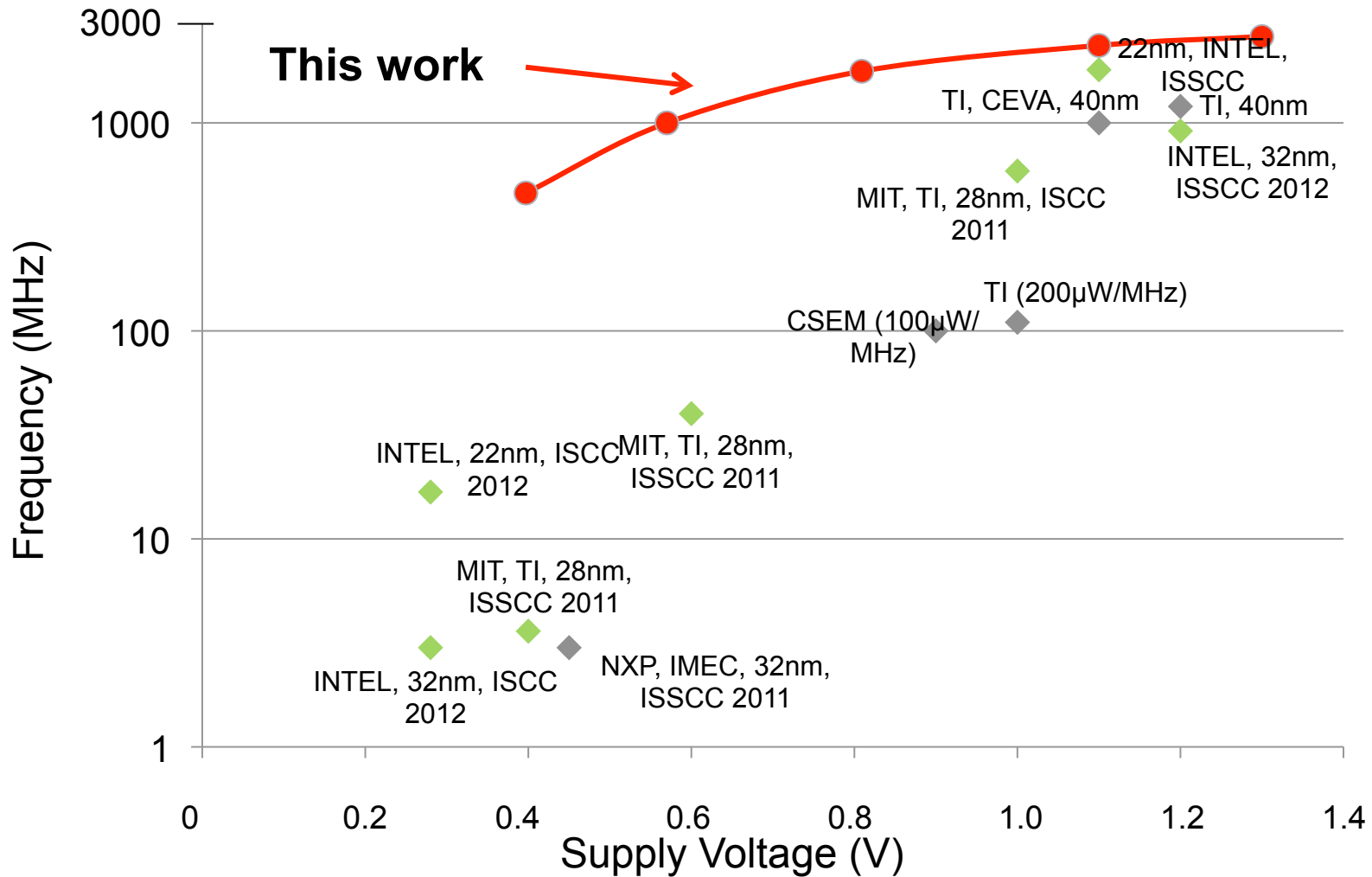
- For a fixed voltage supply :
  - Lowest energy at 460MHz
  - Power consumption : 370mW at 1V



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 27.1 : A 460MHz@397mV – 2.6GHz@1.3V 32bit VLIW DSP Embedding FMAX Tracking



# Comparison with State of the Art WVR





# Thank You!